

International
UON Collider
Collaboration



Collider transverse impedance and stability studies

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Thanks to F. Batsch, F. Boattini, L. Bottura,
D. Calzolari, C. Carli, A. Chancé, H. Damerau,
A. Grudiev, I. Karpov, A. Lechner, K. Skoufaris

Muon collider collaboration – Annual meeting
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Swiss Accelerator
Research and
Technology

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and Technology (CHART) program (www.chart.ch).*

Goal and scope of the study

- Get a first estimate of the **minimum vacuum chamber** radius achievable w.r.t transverse beam stability
- Investigate **different materials** for the chamber
- Important input for the optics, the magnet, the muon decay shielding, the vacuum etc. design (see presentations from K. Skoufaris, L. Bottura, A. Lechner et al.)



Goal and scope of the study

- Simulations first performed for the **3 TeV collider** (1.5 TeV muon beam)
- Second set of simulations for the **10 TeV collider** (5 TeV muon beam)

3 TeV collider: Assumptions and simulation parameters



3 TeV: Impedance simulations parameters

- 1.5 TeV single beam, 4.5 km long beam chamber
- Scan the chamber radius from 10 mm to 40 mm
- Scan the chamber material

Machine parameters

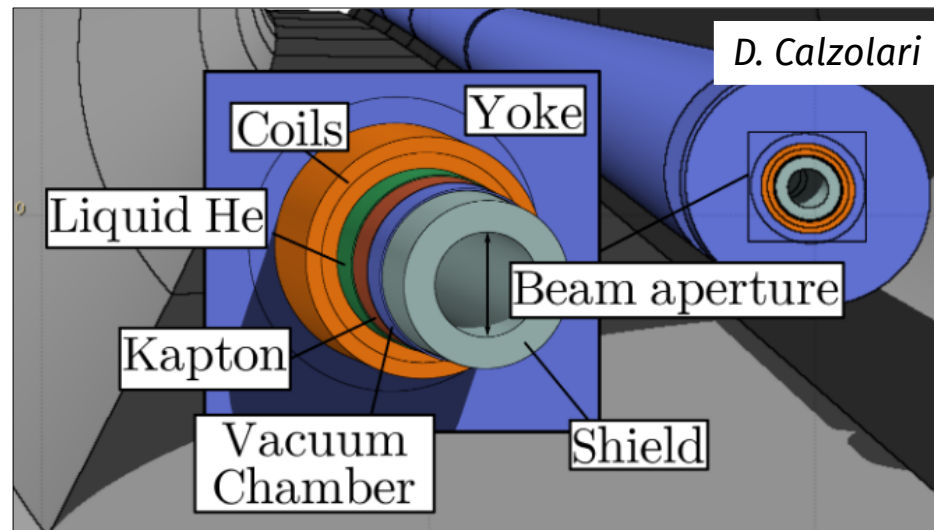
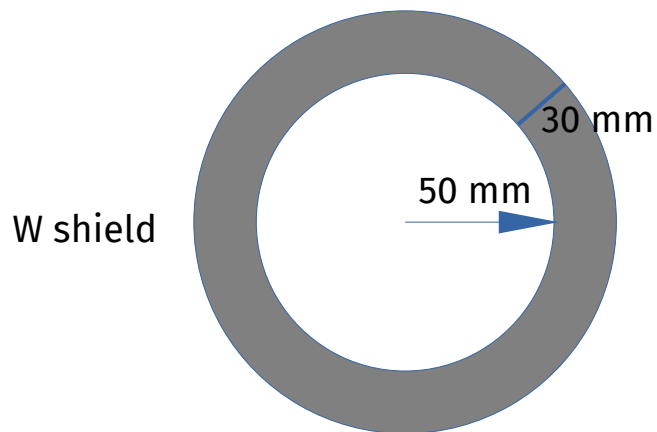
	Unit	Value
Circumference	m	4500
Chamber length	m	4500
Chamber geometry		Circular
Chamber material		Tungsten 300 K / Tungsten 80K Copper 300 K / Copper 20 K
Chamber thickness	m	Inf.
Chamber radius	mm	10 to 40
Avg. beta x/y	m	100 / 100

Materials considered for the beam chamber

- Past Muon collider studies suggested to use a tungsten liner to intercept muon decay products
 - Decrease the heat load and radiation dose sustained by the magnets
 - Proposal for a liner cooled at 80 K by [N. V. Mokhov et al.](#)
 - Also proposal for a tungsten liner at 300 K, see [M. Green](#)

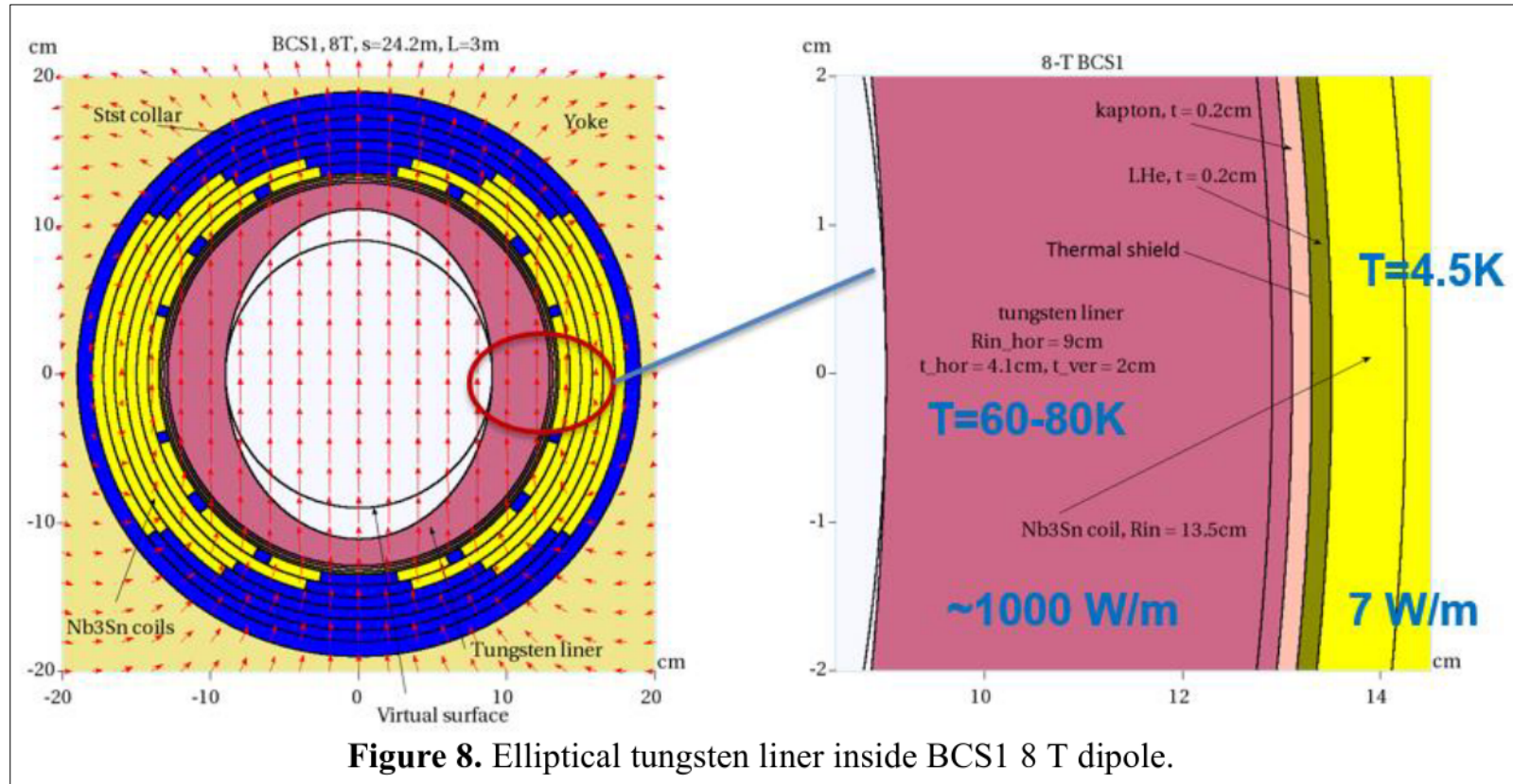
Liner design to protect from muon decay product

- Power deposition and radiation damage studies done by D. Calzolari et al., presented at IPAC 22 (see also his presentation today)
- 30 mm thick, 50 mm inner radius, tungsten shield
- Shield temperature not yet defined

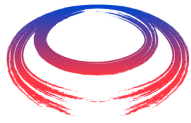


Liner design to protect from decay product

Liner thickness varies according to magnet type and family

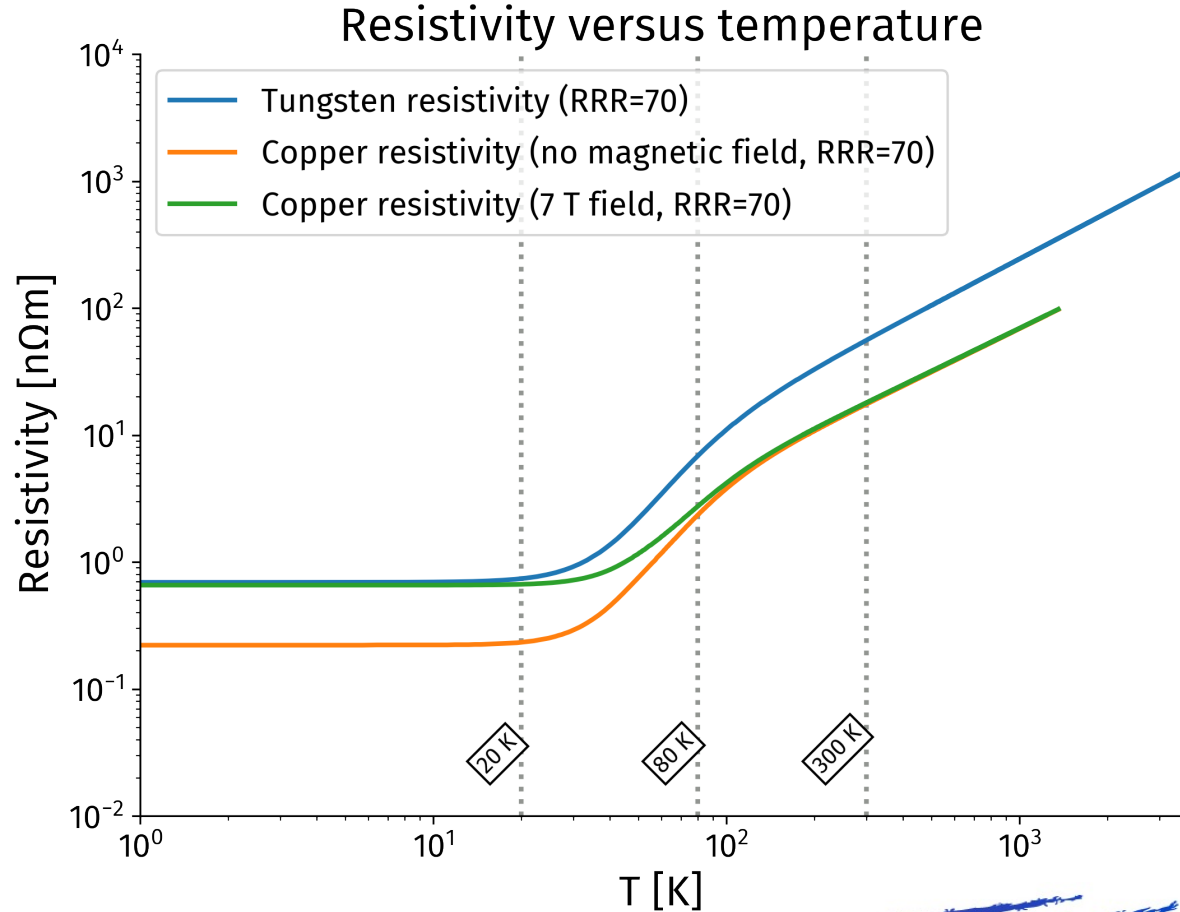


*Tungsten liner design from
N. V. Mokhov et al.*



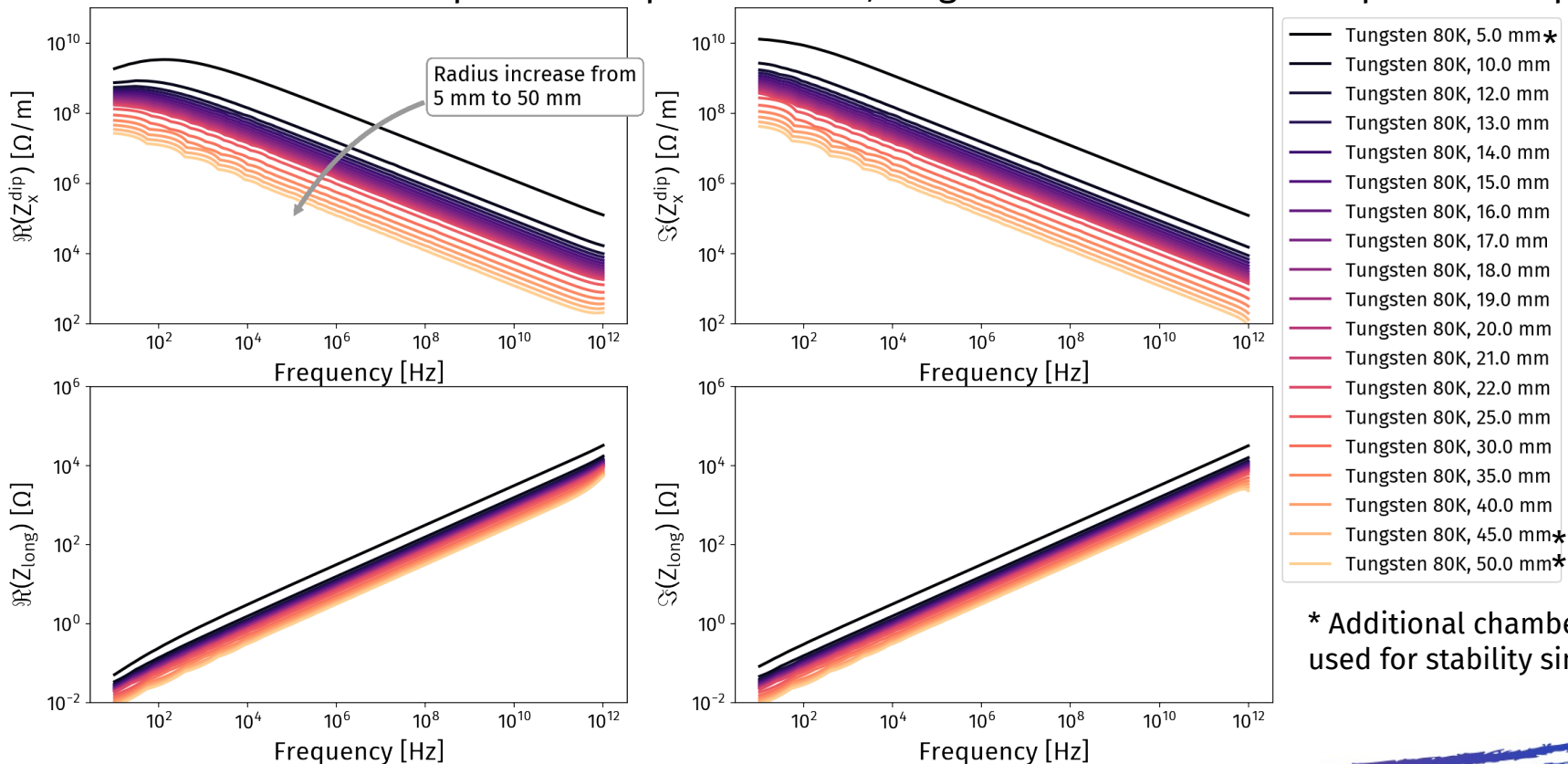
Impedance simulations parameters: materials

- Resistive wall impedance and wake are proportional to $\sqrt{\rho}$
- Copper and tungsten resistivity versus temperature and RRR from:
 - Simon, Drexler and Reed “Properties of copper and copper alloys at cryogenic temperatures”, 1992
 - Hust and Landford, “Thermal Conductivity of Aluminum, Copper, Iron, and Tungsten for Temperatures from 1 K to the Melting Point”, 1984
- A copper coating/lining would help reduce the vacuum chamber impedance



Impedance results for chambers in Tungsten at 80 K

Transverse resistive wall impedance depends on $1/r^3$, longitudinal resistive wall impedance depends on $1/r$





Transverse stability simulation parameters in the 3 TeV collider

- Simulation including transverse map + longitudinal map (1 RF station) + **transverse wakefield + damper + muon decay**
- Tracking over 3000 turns, 5000 macroparticles with PyHEADTAIL, initial intensity **$2.2 \cdot 10^{12}$ muons**, transverse emittance **$25 \mu\text{m rad}$** (detailed parameters in appendix)
- Chromaticity is corrected to 0/0 (**natural chromaticity is compensated**), no Landau octupoles included
- **Optionally: include muon decay effect**
 - Muon lifetime at 1.5 TeV: $14285 * 2.2 \mu\text{s} = 31.4 \text{ ms}$
 - Revolution frequency $\sim 66 \text{ kHz}$ → **muon lifetime at 1.5 TeV is ~ 2100 turns**

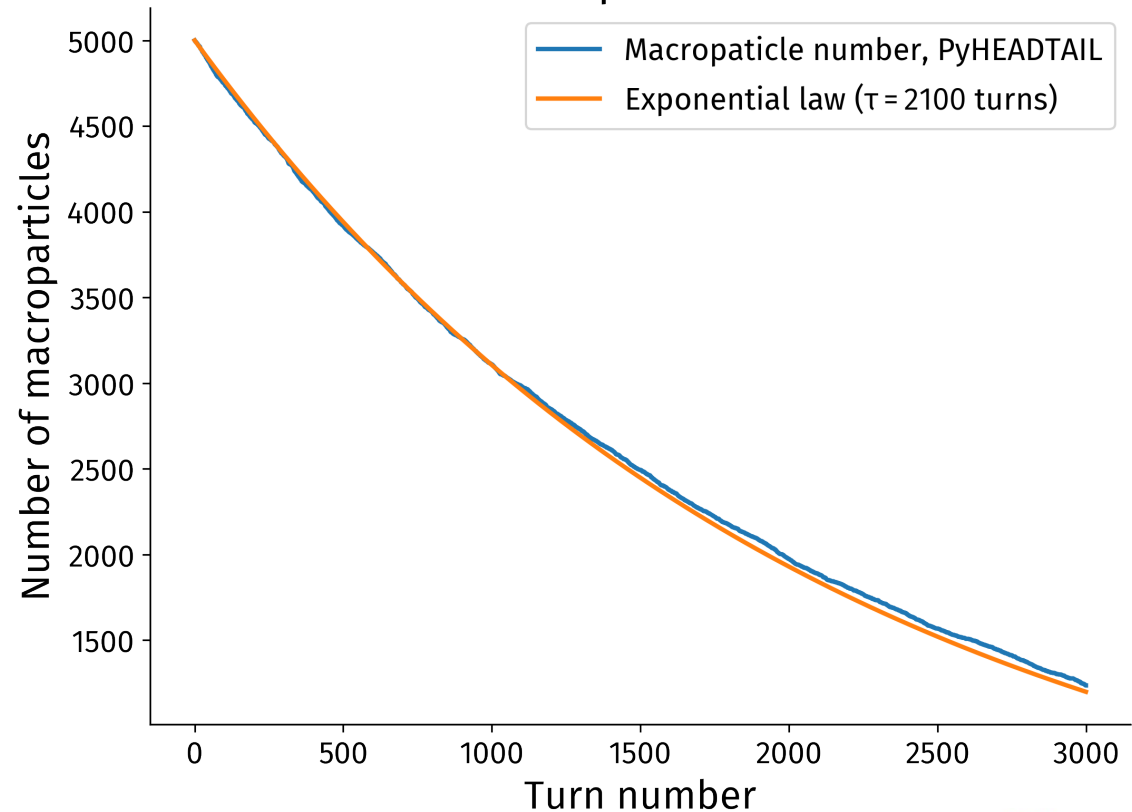
Transverse stability simulation parameters in the 3 TeV collider

- Scan the **chamber radius from 10 mm to 40 mm**
- Scan the transverse damper gain from 2 to 500-turn damping time
+ no damper
- Horizontal and vertical planes have the same impedance (circular chamber), and same beam parameters → simulation results identical in the two planes

Implementation of the muon beam decay

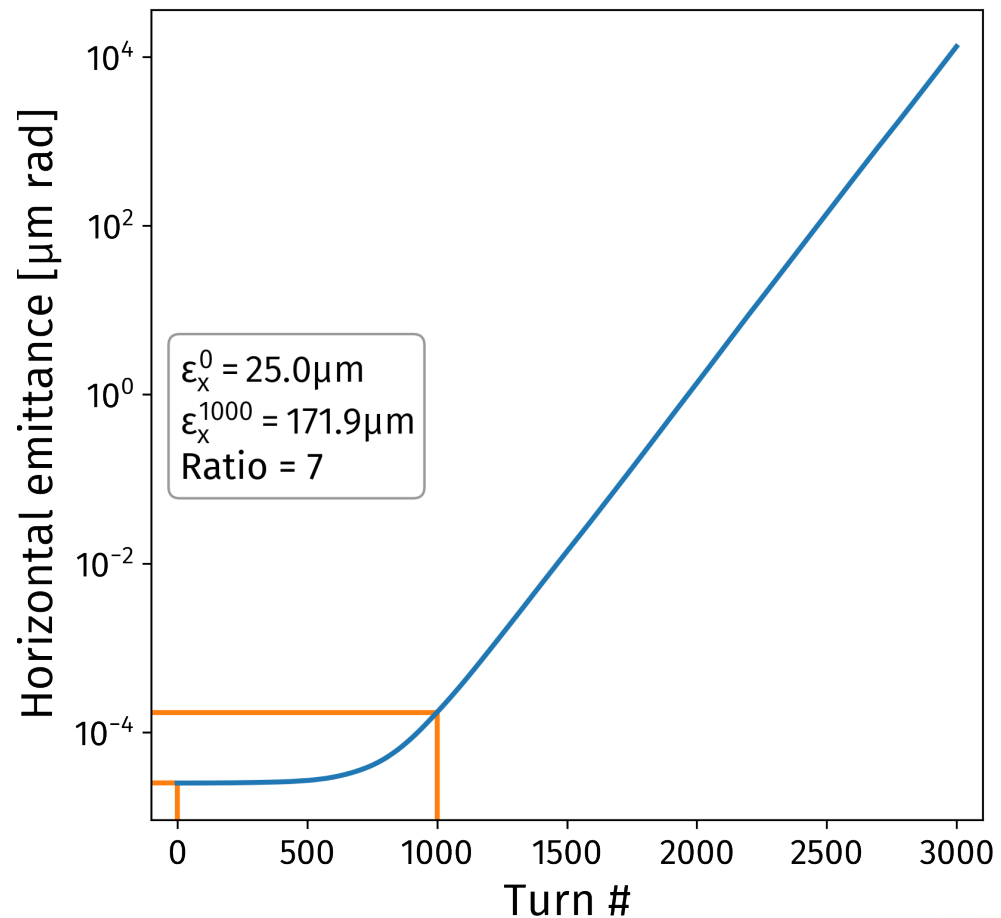
- Decay element in PyHEADTAIL
 - Input: decay time (in number of turns) of the beam
 - Use numpy rand function to randomly select the macroparticles that will be deleted, according to the decay time
- Exponential decay behavior reproduced in simulations
- Bunch intensity reduced by 50 % after $\ln(2) \cdot 2100 = 1450$ turns

Comparison of macroparticle decay versus exponential law



Growth ratio plots

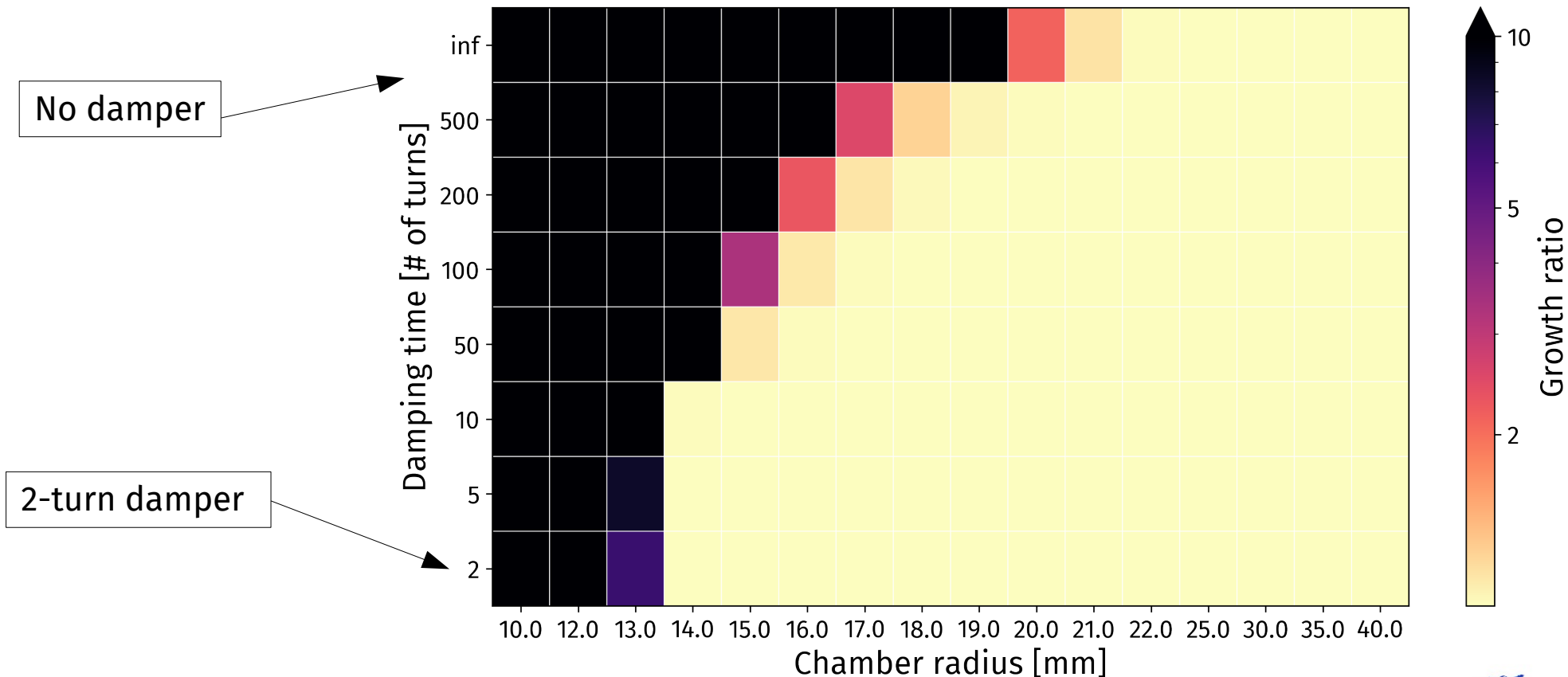
- Compute the ratio of emittance after a certain time versus initial emittance (25 $\mu\text{m rad}$)
- For all damper settings and chamber radius, at different number of turns
- We will look at growth ratios after 2000 turns



3 TeV collider: Simulation results

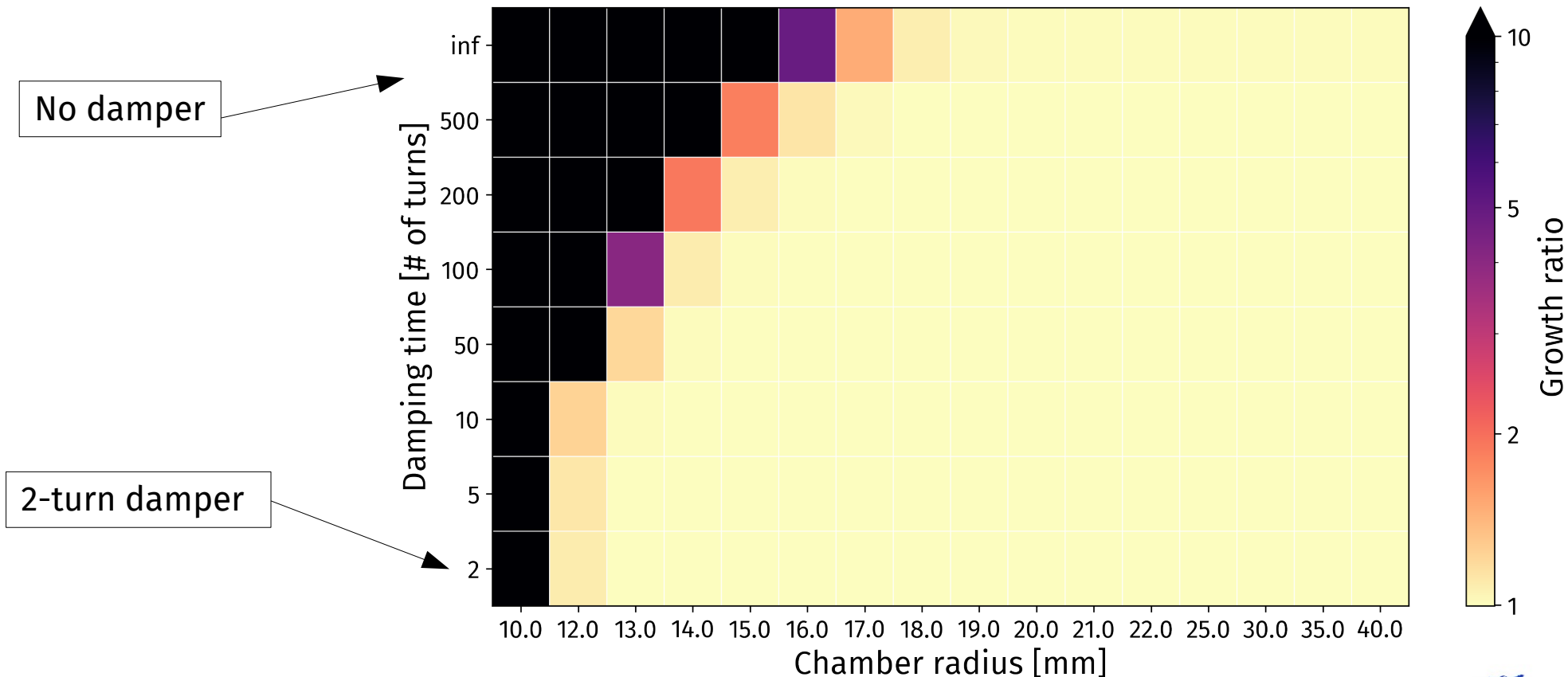
Tungsten 80 K, WITHOUT muon decay

Tungsten at 80 K growth ratio after 2000 turns



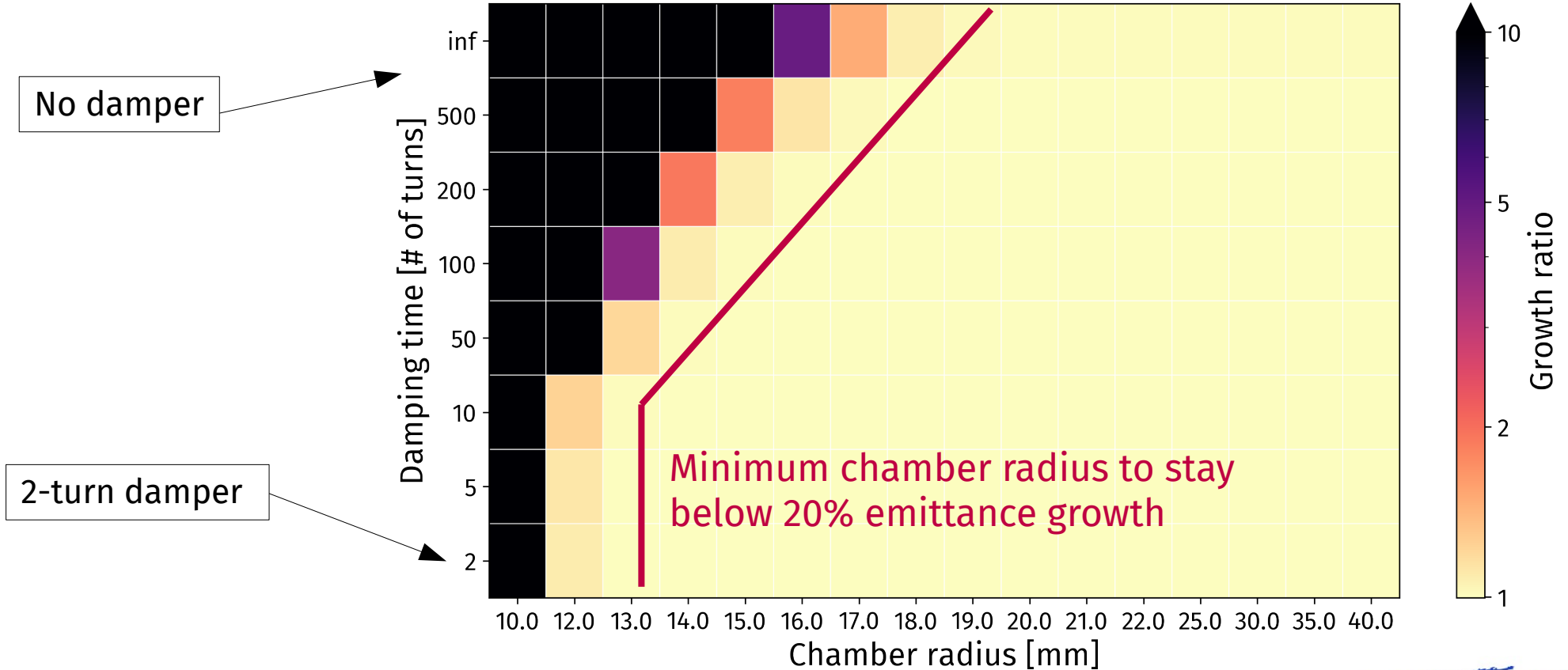
Tungsten 80 K, WITH muon decay

Tungsten at 80 K, with muon decay growth ratio after 2000 turns



Tungsten 80 K, WITH muon decay

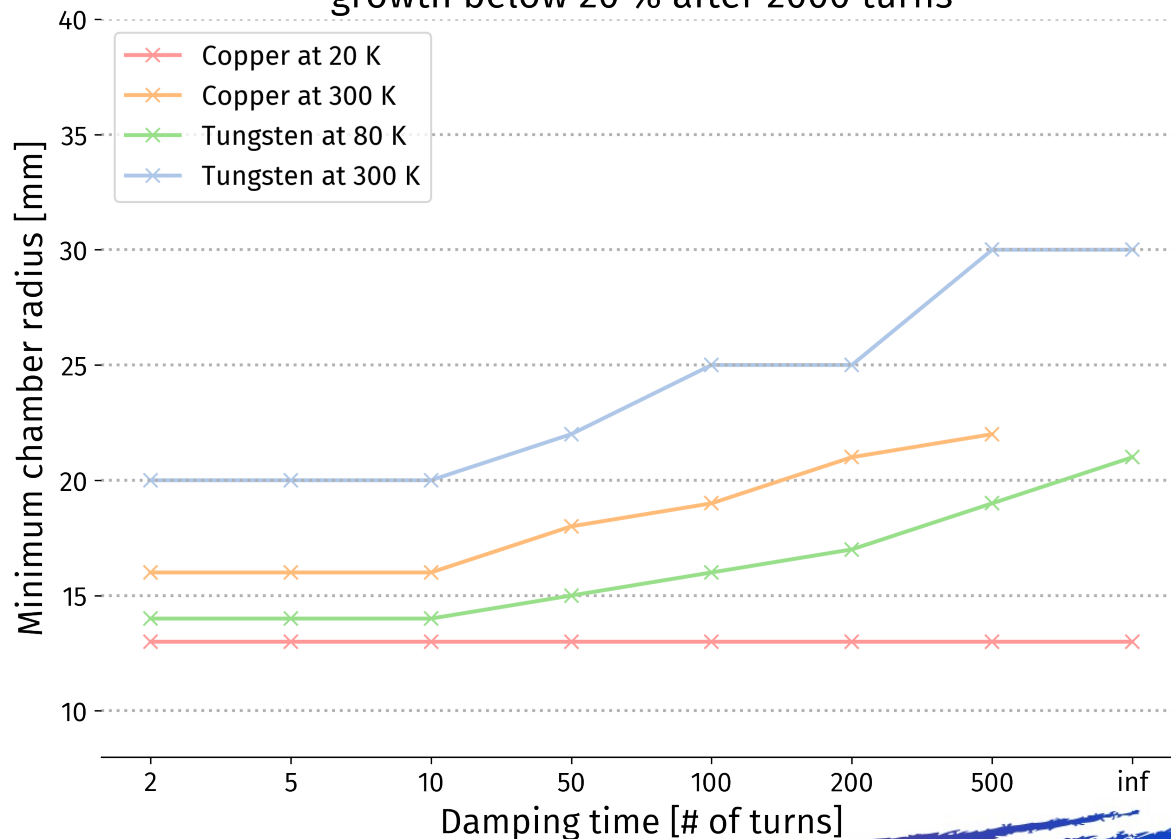
Tungsten at 80 K, with muon decay growth ratio after 2000 turns



Minimum chamber radius versus material, without muon decay

- Summary plot for the case **without muon decay**
- For every damper gain, find the chamber radius such as the **emittance growth stays below 20 % after 2000 turns**
 - No point for a damper setting means that the beam was always unstable

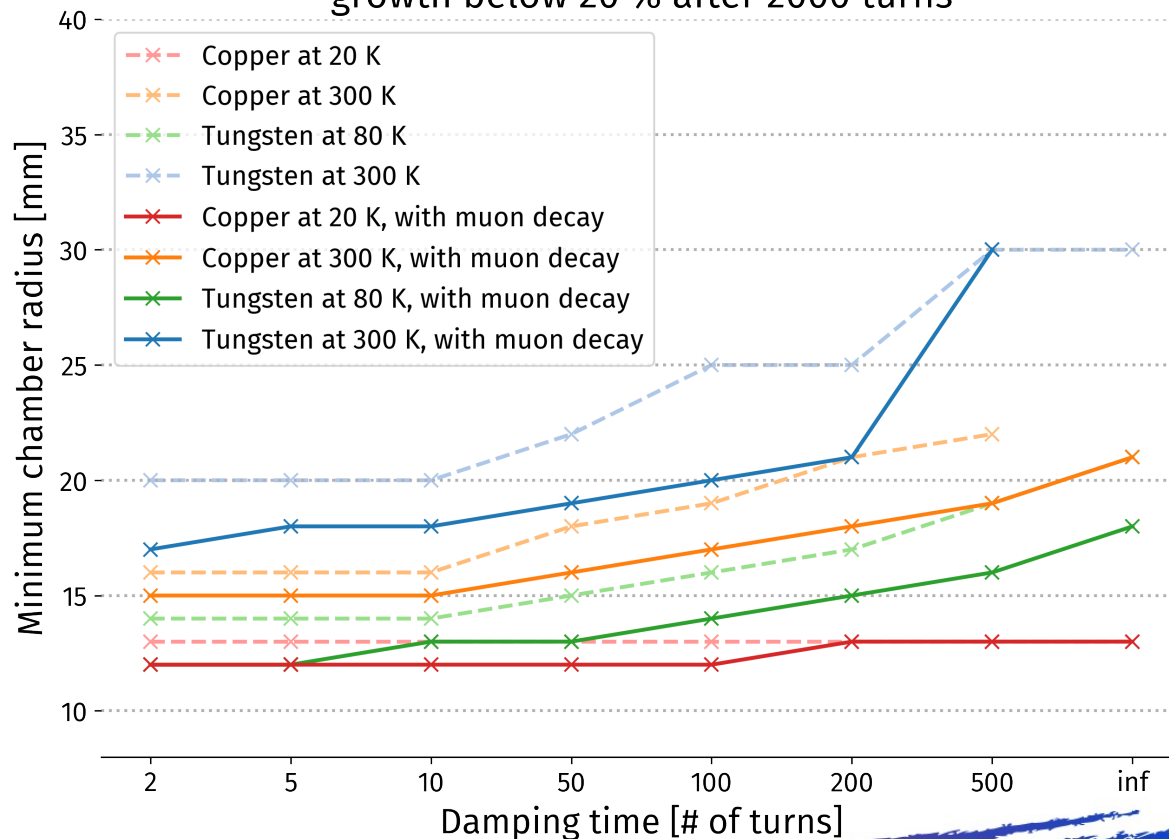
Chamber radius to keep emittance growth below 20 % after 2000 turns



Minimum chamber radius versus material, with muon decay

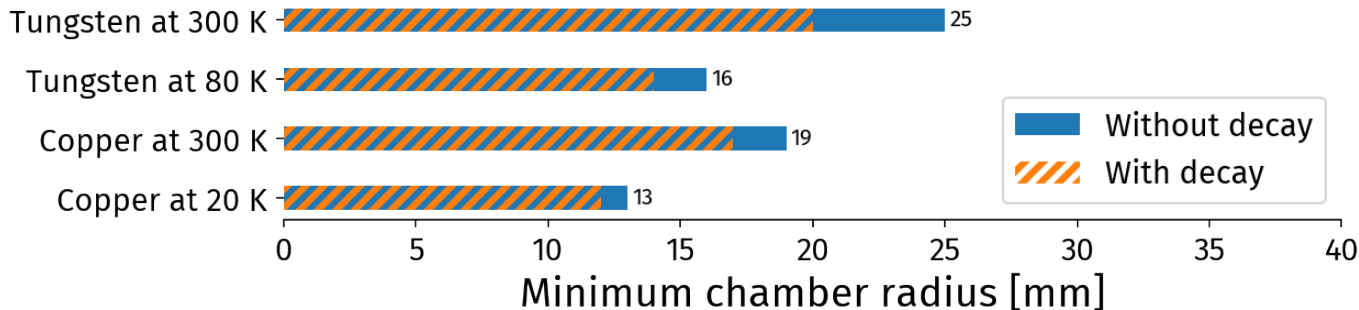
- Summary plot for the case **without and with muon decay**
- For every damper gain, find the chamber radius such as the **emittance growth stays below 20 % after 2000 turns**
 - No point for a damper setting means that the beam was always unstable

Chamber radius to keep emittance growth below 20 % after 2000 turns



Minimum chamber radius versus material

Chamber radius to keep emittance
growth below 20 % after 2000 turns (100-turn damper)



- With a 100-turn damper transverse beam stability would require at least **25 mm radius with Tungsten at 300 K for the 3 TeV collider (without decay)**
- A copper pipe allows to go below 20 mm radius: copper lining or coating would help stability
- Muon decay adds some margin on the radius (up to 5 mm)

10 TeV collider: Assumptions and simulation parameters

10 TeV: Impedance simulations parameters

- 5 TeV per beam, 10 km long beam chamber
- Other parameters are also **modified**: average beta functions (input from optics design by K. Skoufaris), Copper at 80 K instead of 20 K

Machine parameters

	Unit	Value
Circumference	m	10000
Chamber length	m	10000
Chamber geometry		Circular
Chamber material		Tungsten 300 K / Tungsten 80K Copper 300 K / Copper 80 K
Chamber thickness	m	Inf.
Chamber radius	mm	10 to 40
Avg. beta x/y	m	85 / 51



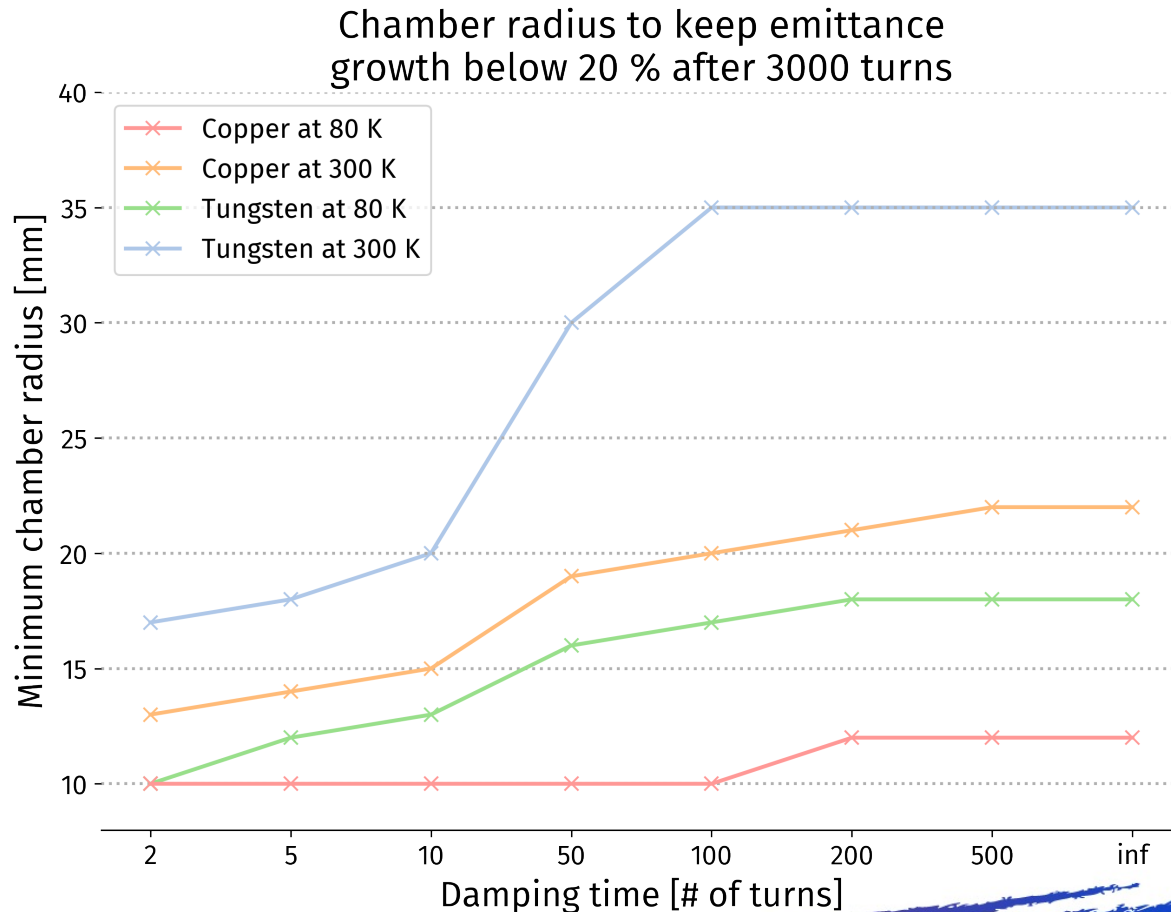
Transverse stability simulation parameters in the 10 TeV collider

- Simulation including transverse map + longitudinal map (1 RF station) + **transverse wakefield + damper + muon decay**
- Tracking over **5000 turns**, **20000 macroparticles** with PyHEADTAIL, initial intensity **$1.8 \cdot 10^{12}$ muons**, transverse emittance **25 $\mu\text{m rad}$** (detailed parameters in appendix)
- **Optionally: include muon decay effect**
 - Muon lifetime at 5 TeV: $47323 \cdot 2.2 \mu\text{s} = 104 \text{ ms}$
 - Revolution frequency $\sim 30 \text{ kHz}$ \rightarrow **muon lifetime at 5 TeV is ~ 3120 turns**

10 TeV collider: Simulation results

Minimum chamber radius versus material, without muon decay

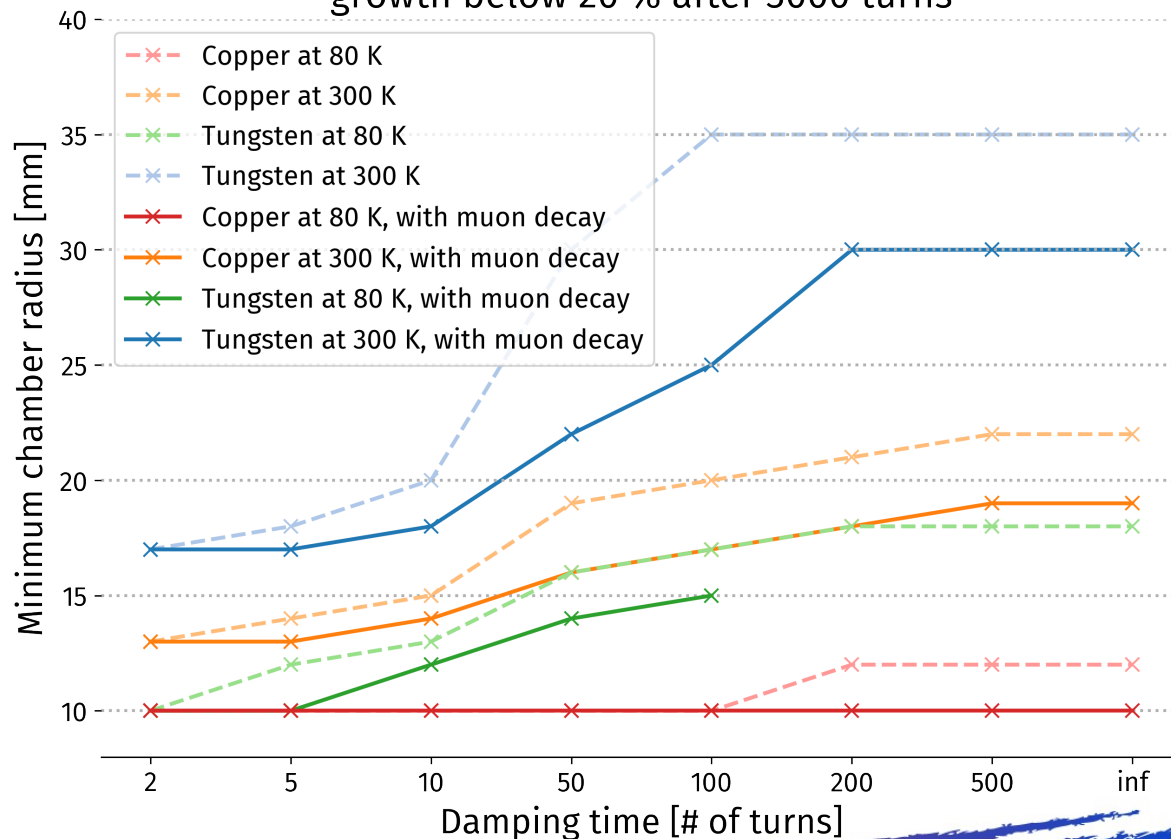
- Summary plot for the case **without muon decay**
- For every damper gain, find the chamber radius such as the **emittance growth** stays **below 20 % after 3000 turns**
 - No point for a damper setting means that the beam was always unstable



Minimum chamber radius versus material, with muon decay

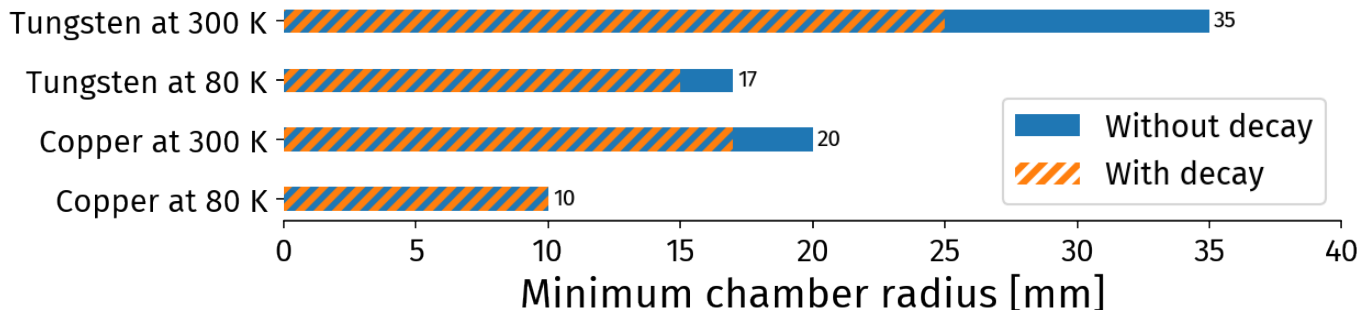
- Summary plot for the case **without and with muon decay**
- For every damper gain, find the chamber radius such as the **emittance growth stays below 20 % after 3000 turns**
 - No point for a damper setting means that the beam was always unstable

Chamber radius to keep emittance growth below 20 % after 3000 turns

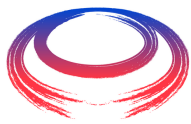


Minimum chamber radius versus material

Chamber radius to keep emittance
growth below 20 % after 3000 turns (100-turn damper)



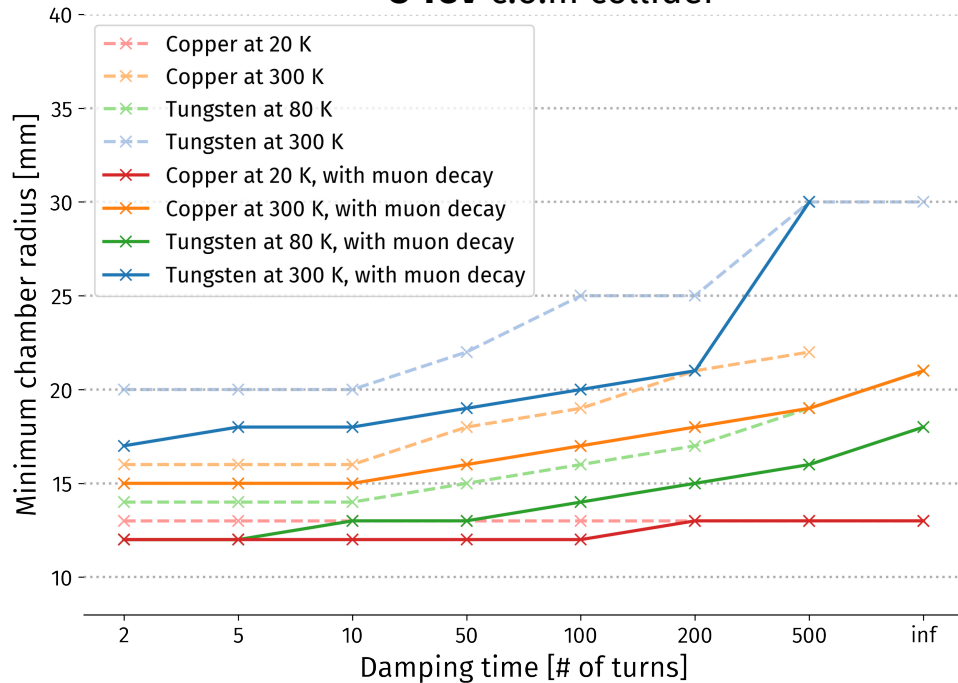
- With a 100-turn damper transverse beam stability would require at least **35 mm radius with Tungsten at 300 K for the 10 TeV collider (without decay)**
- A copper pipe allows to go to 20 mm radius range: copper lining or coating would help stability
- Muon decay adds some margin on the radius (up to 5 mm)



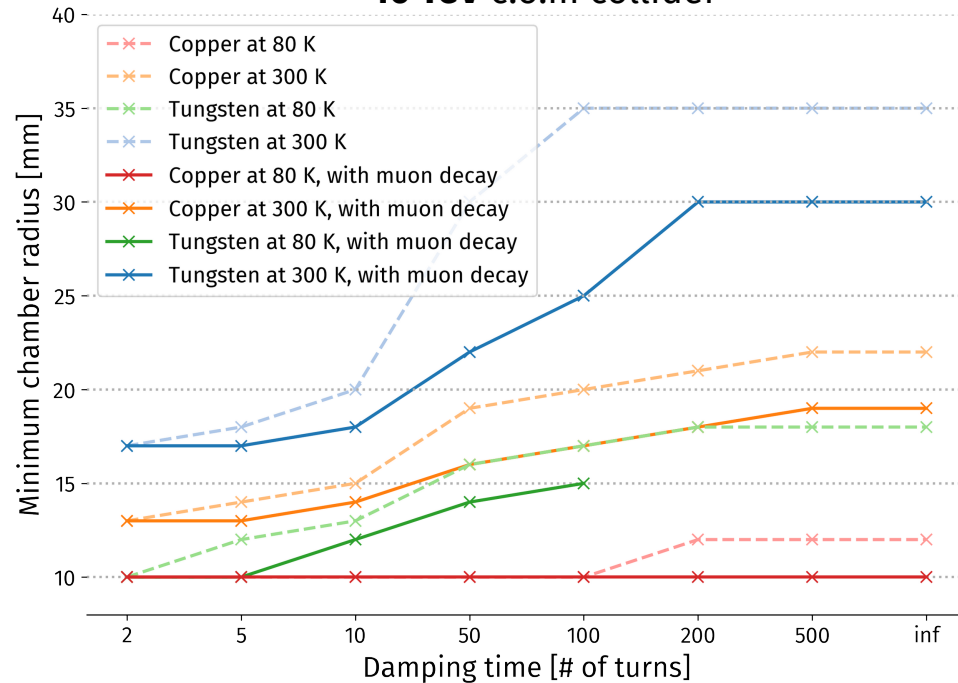
Conclusion

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3 TeV c.o.m collider



10 TeV c.o.m collider

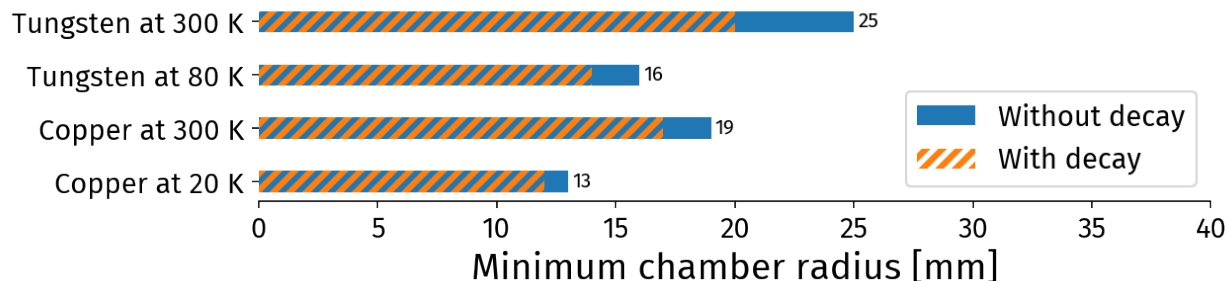


- Overall the 10 TeV collider requires larger apertures than the 3 TeV collider with Tungsten at 300 K
- Muon decay helps gaining some margin on the minimum chamber radius required for transverse stability

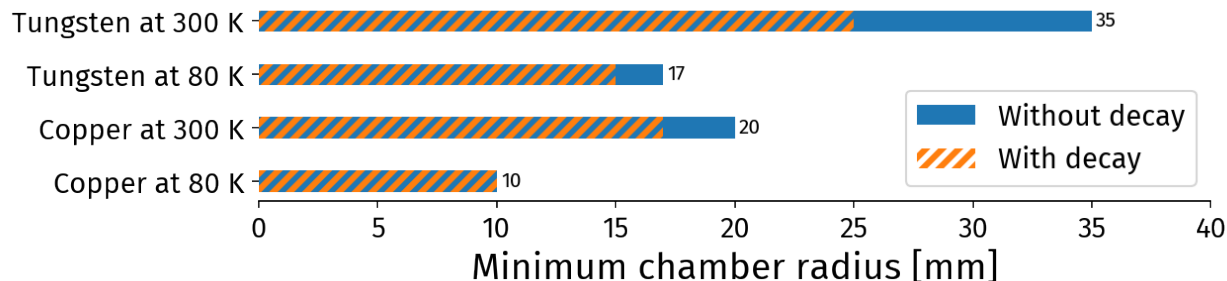
Conclusion

- With a 100-turn damper transverse beam stability would require at least **35 mm radius with Tungsten at 300 K for the 10 TeV collider (without decay), 25 mm when including muon decay**
- A copper pipe allows to go to 20 mm radius range: copper lining or coating would help stability

3 TeV c.o.m collider, 100-turn damper



10 TeV c.o.m collider, 100-turn damper





Next steps for the colliders

- Include additional instability mitigation measures to help reach tighter chamber radii (positive chromaticity, Landau damping with octupoles)
- Simulate a more detailed vacuum chamber built when the first specifications are found
 - Interaction with optics, magnet, shielding, vacuum etc. to define the required apertures (see K. Skoufaris, L. Bottura, A. Lechner et al.)
- Include the second, counter-rotating, beam effects
- Investigate other potential shielding materials
 - Suggestion from P. Sievers: Tungsten-Copper, Tungsten-Rhenium, Tantalum...

Thanks for your attention

Appendix: 3TeV collider

Impedance simulations parameters: materials

- Infinite thickness for all the chambers simulated

Copper at 20 K

	Unit	Value
Magnetic field	T	7
Temperature	K	20
RRR		70
DC resistivity	nOhm m	0.667

Copper at 300 K

	Unit	Value
Magnetic field	T	7
Temperature	K	300
RRR		70
DC resistivity	nOhm m	17.9

Tungsten at 80 K

	Unit	Value
Temperature	K	80
DC resistivity	nOhm m	6.06

Tungsten at 300 K

	Unit	Value
Temperature	K	300
DC resistivity	nOhm m	54.4

Stability simulation parameters

Machine parameters

	Unit	Value
Circumference	m	4500
Beam momentum	GeV/c	1500
Rev. frequency	kHz	66
RF frequency	MHz	800
Harmonic number		12008
RF voltage	MV	250
α_p		-2.15e-6
Avg. beta x/y	m	100 / 100
Chromaticity Q'_x/Q'_y		0 / 0
Detuning from octupoles x/y	m^{-1}	0 / 0

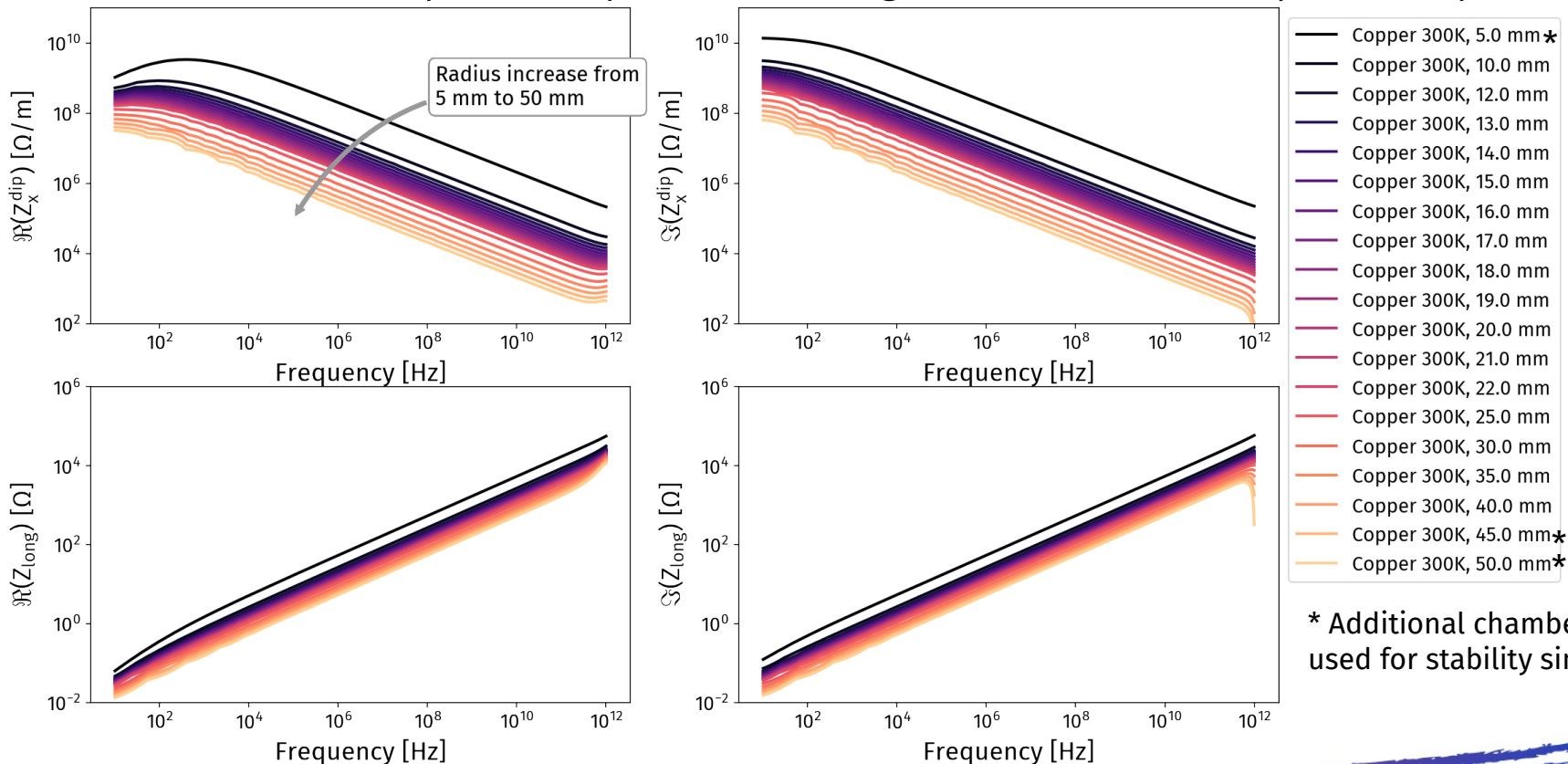
	Unit	Value
Synchrotron tune Q_s		0.000829
Synchrotron period	turns	1206
Bunch length 1σ	mm	5
Bunch intensity	Particles per bunch	2.2e12
ϵ_x / ϵ_y	$\mu\text{m rad}$	25
# of macroparticles		5000

Scanned parameters

	Unit	Value
Chamber radius	mm	10 to 40
Transverse damper		2 to 500 turns/No damper

Impedance for Copper at 300 K

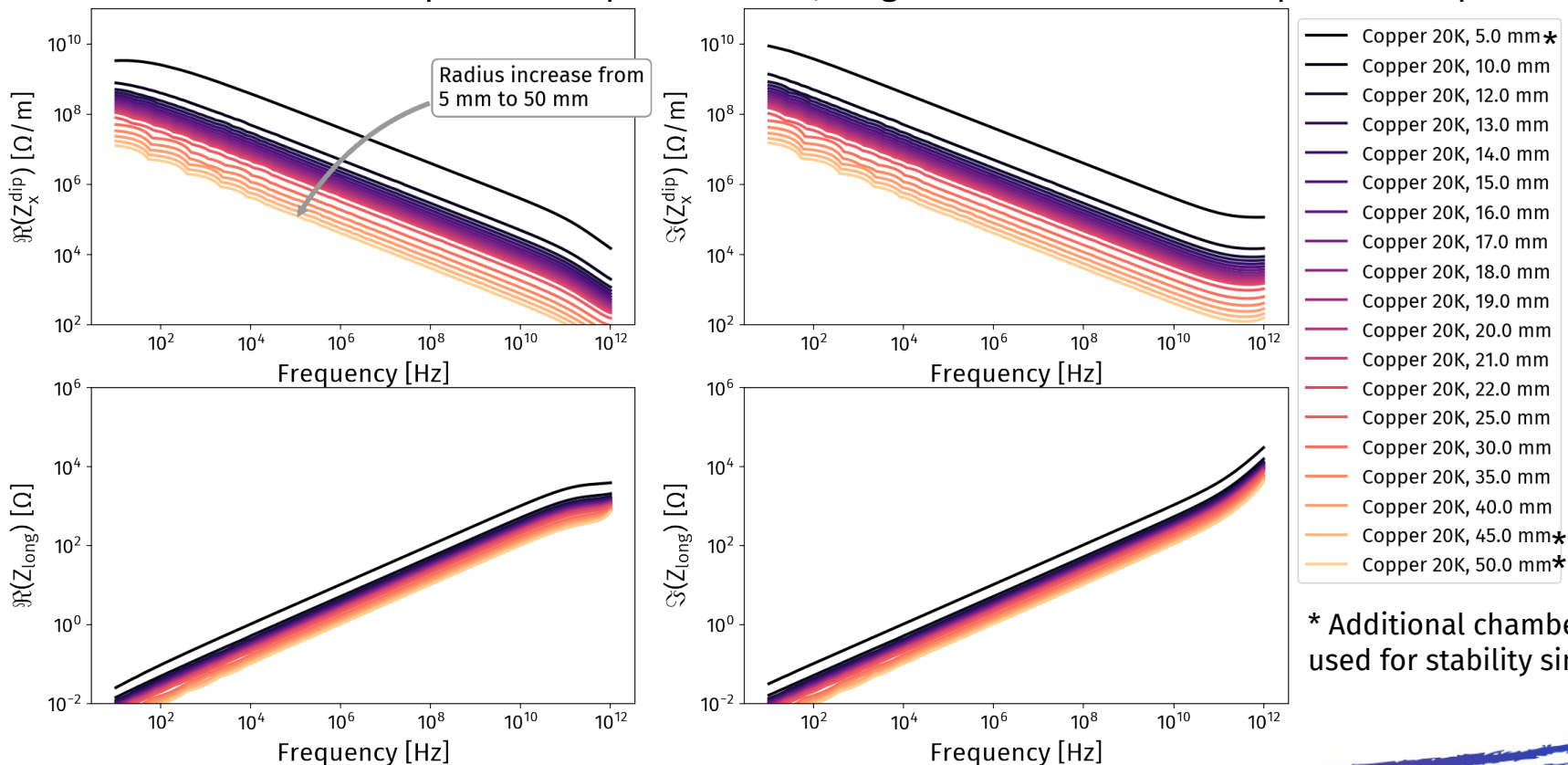
Transverse resistive wall impedance depends on $1/r^3$, longitudinal resistive wall impedance depends on $1/r$



* Additional chamber radii not used for stability simulations

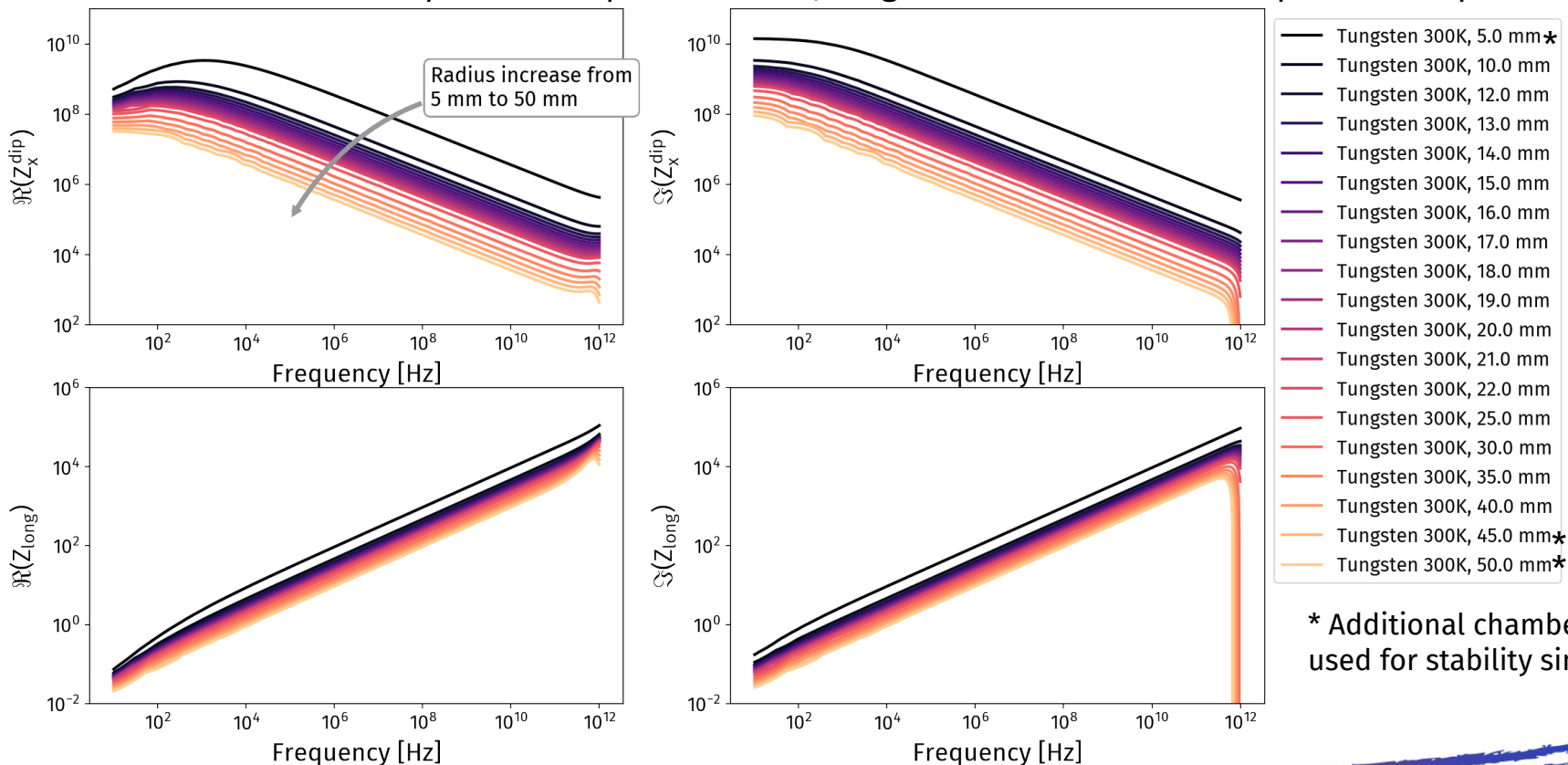
Impedance for Copper at 20 K

Transverse resistive wall impedance depends on $1/r^3$, longitudinal resistive wall impedance depends on $1/r$



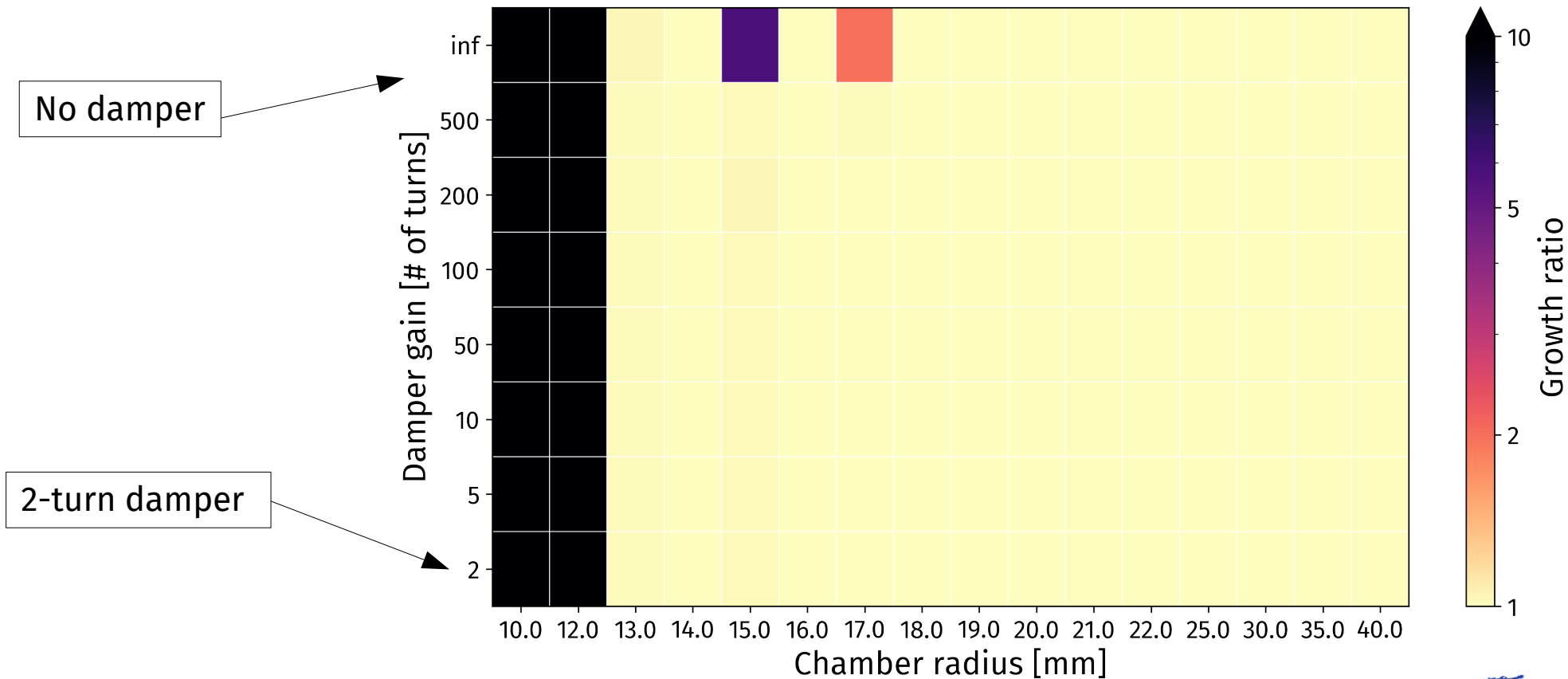
Impedance for Tungsten at 300 K

Transverse resistive wall impedance depends on $1/r^3$, longitudinal resistive wall impedance depends on $1/r$



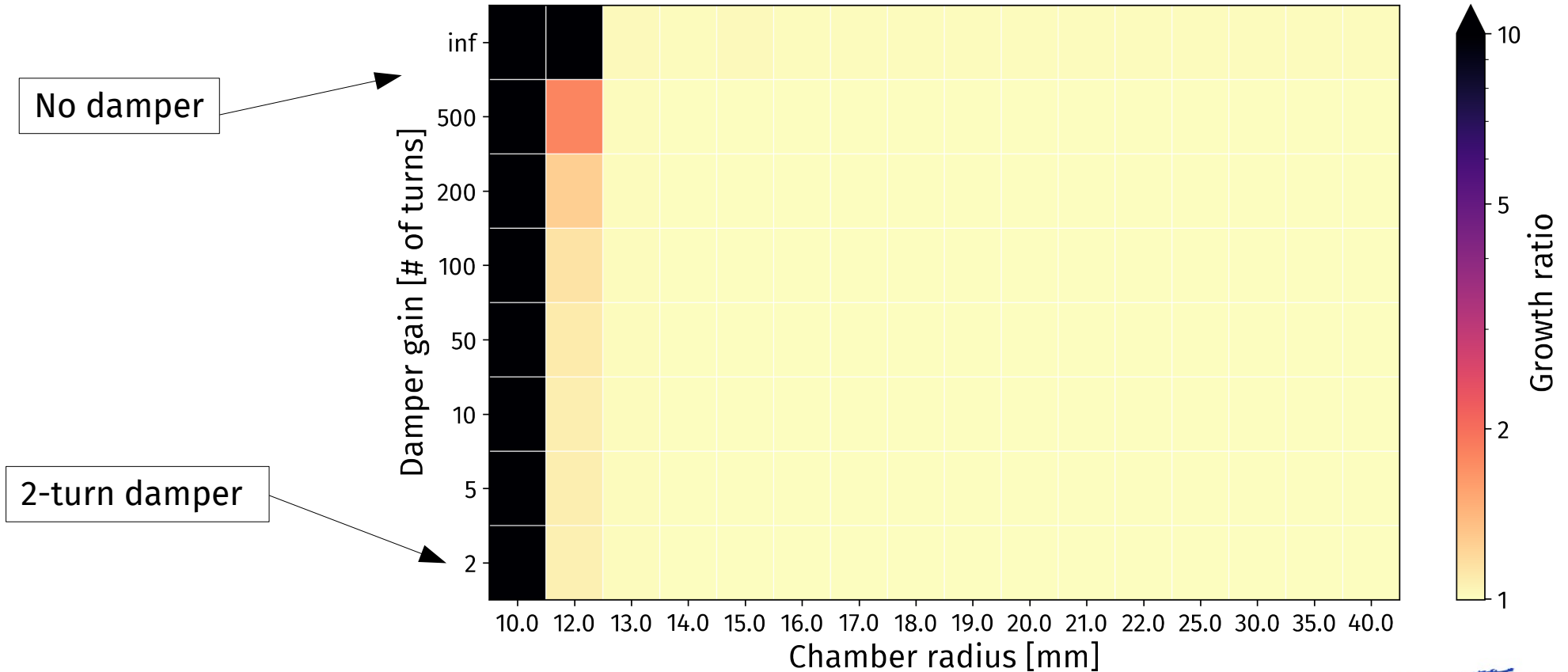
Copper 20 K, after 2000 turns

Copper at 20 K growth ratio after 2000 turns



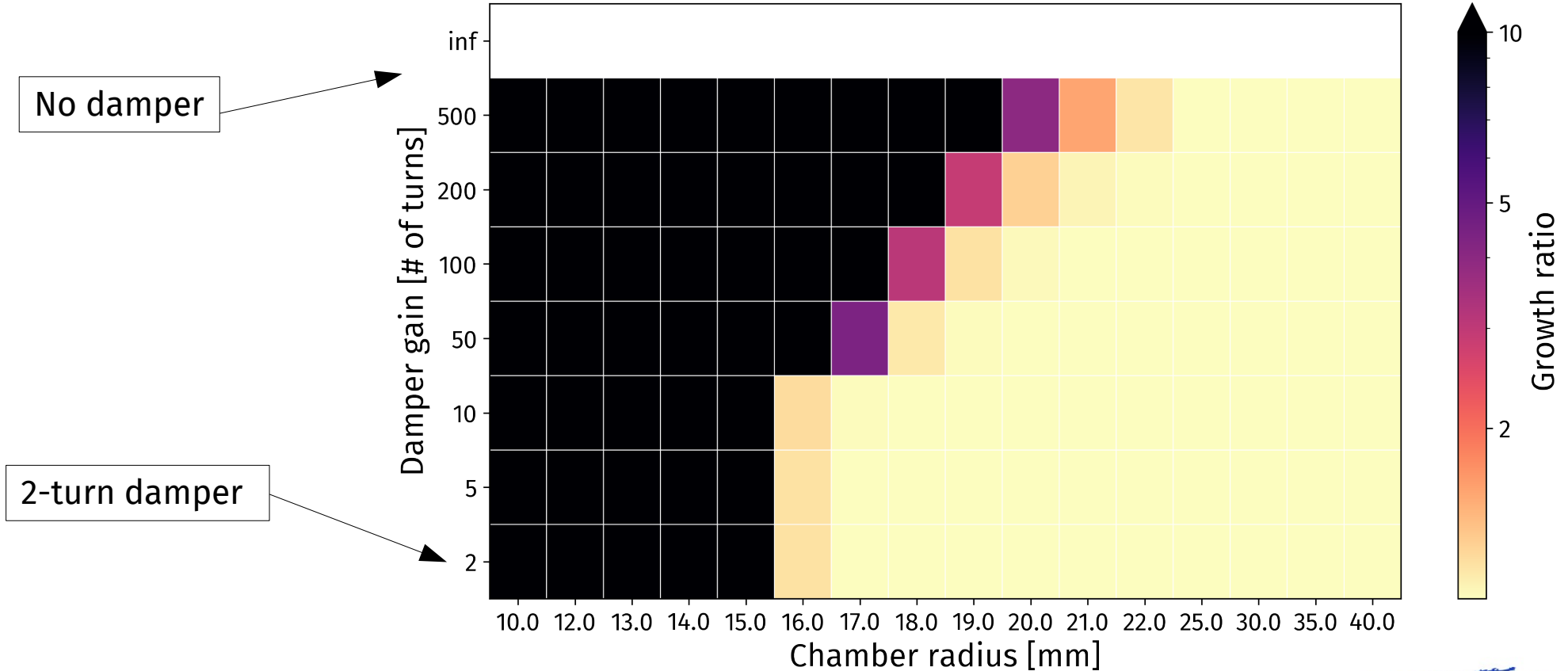
Copper 20 K, after 2000 turns, with muon decay

Copper at 20 K, with muon decay growth ratio after 2000 turns



Copper 300 K, after 2000 turns

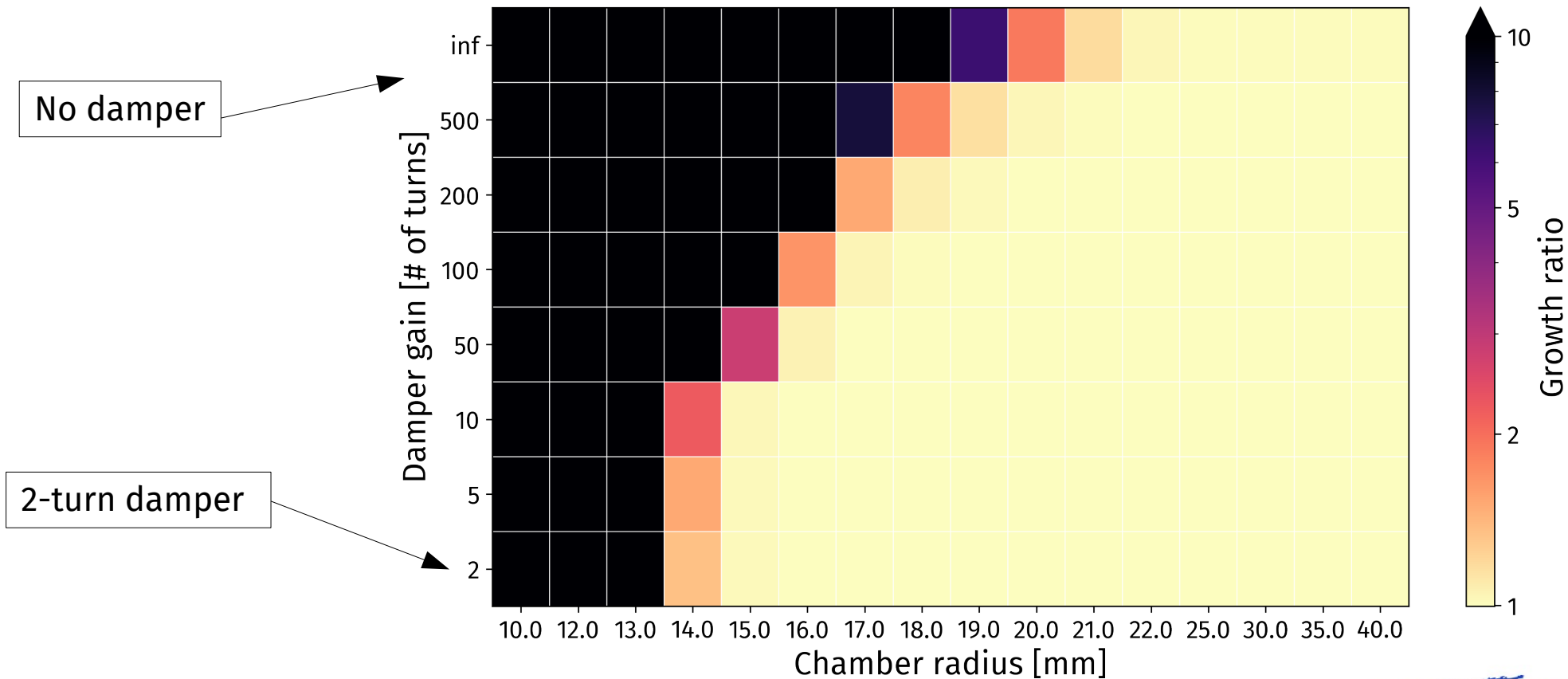
Copper at 300 K growth ratio after 2000 turns



Copper 300 K, after 2000 turns, with muon decay

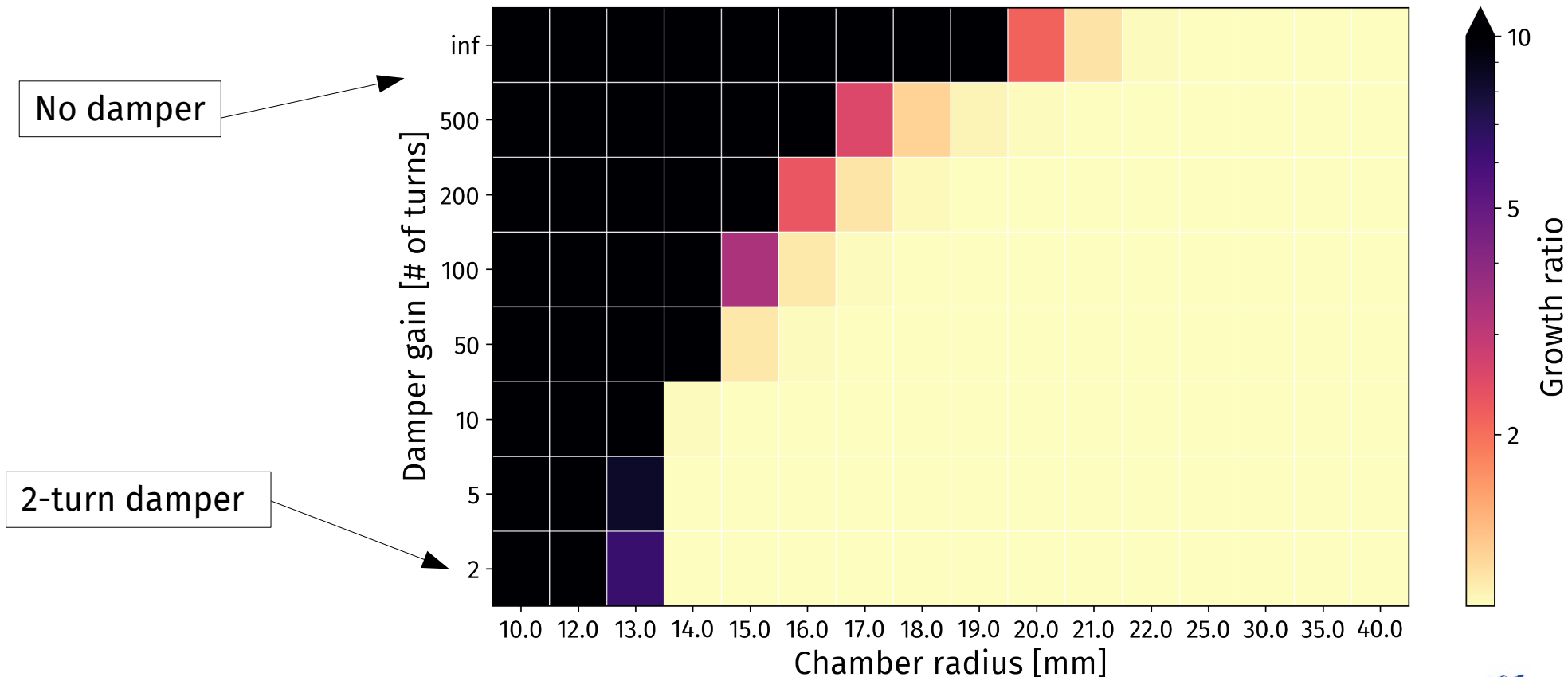
decay

Copper at 300 K, with muon decay growth ratio after 2000 turns



Tungsten 80 K, after 2000 turns

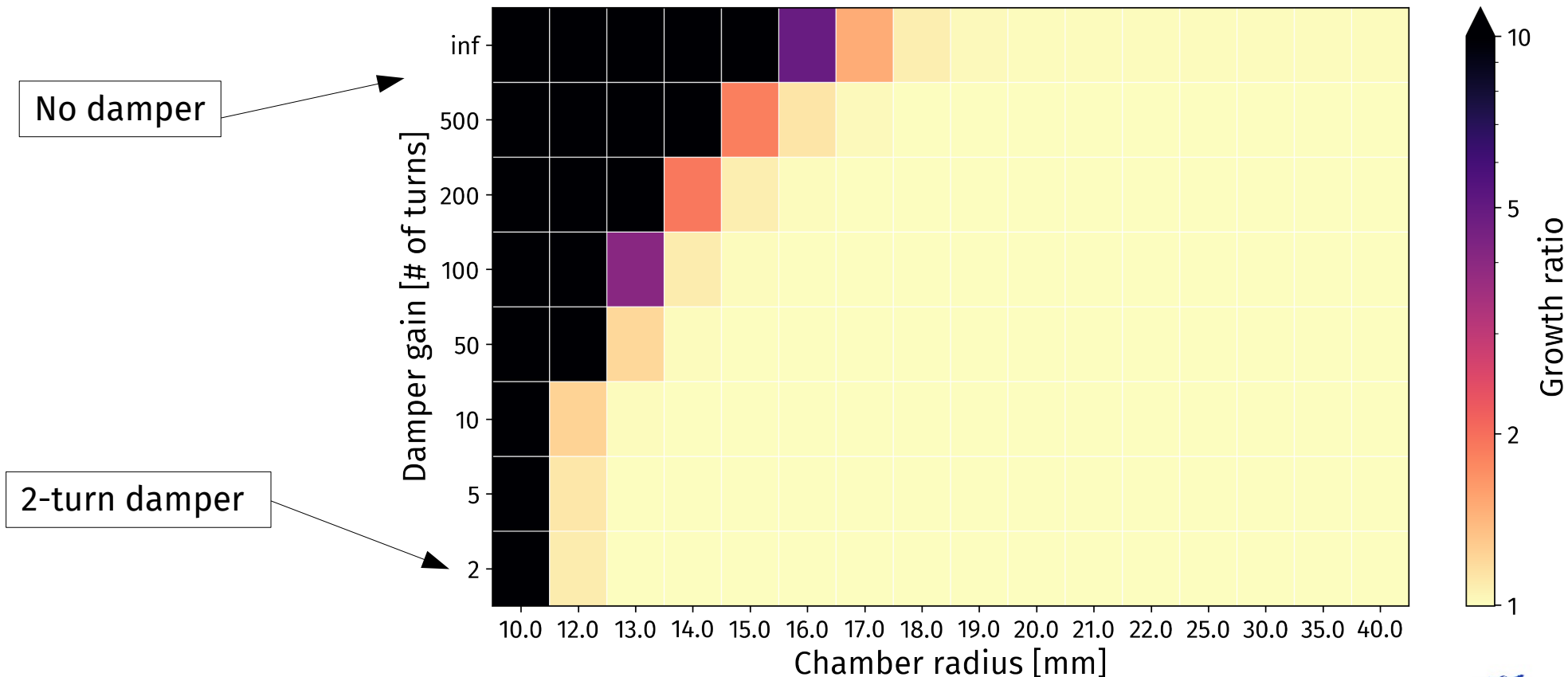
Tungsten at 80 K growth ratio after 2000 turns



Tungsten 80 K, after 2000 turns, with muon decay

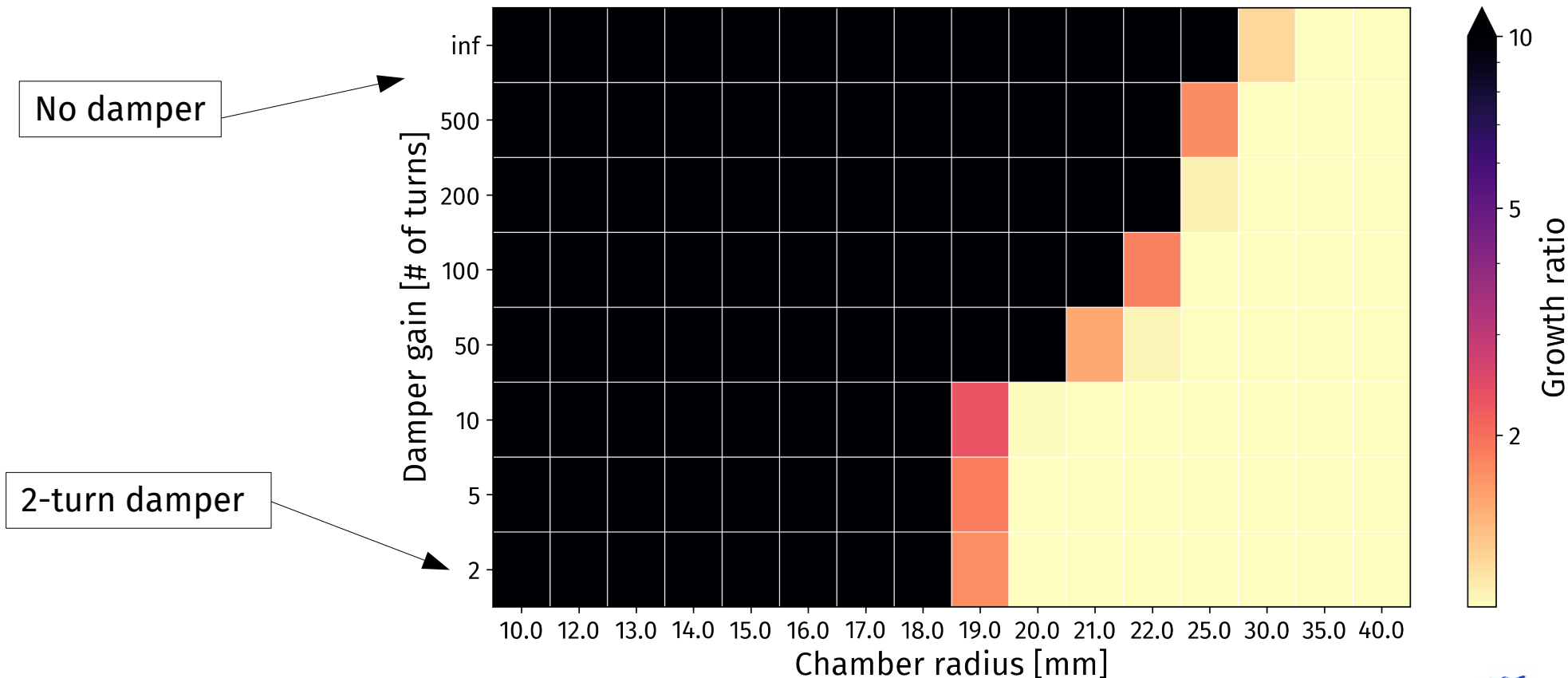
decay

Tungsten at 80 K, with muon decay growth ratio after 2000 turns



Tungsten 300 K, after 2000 turns

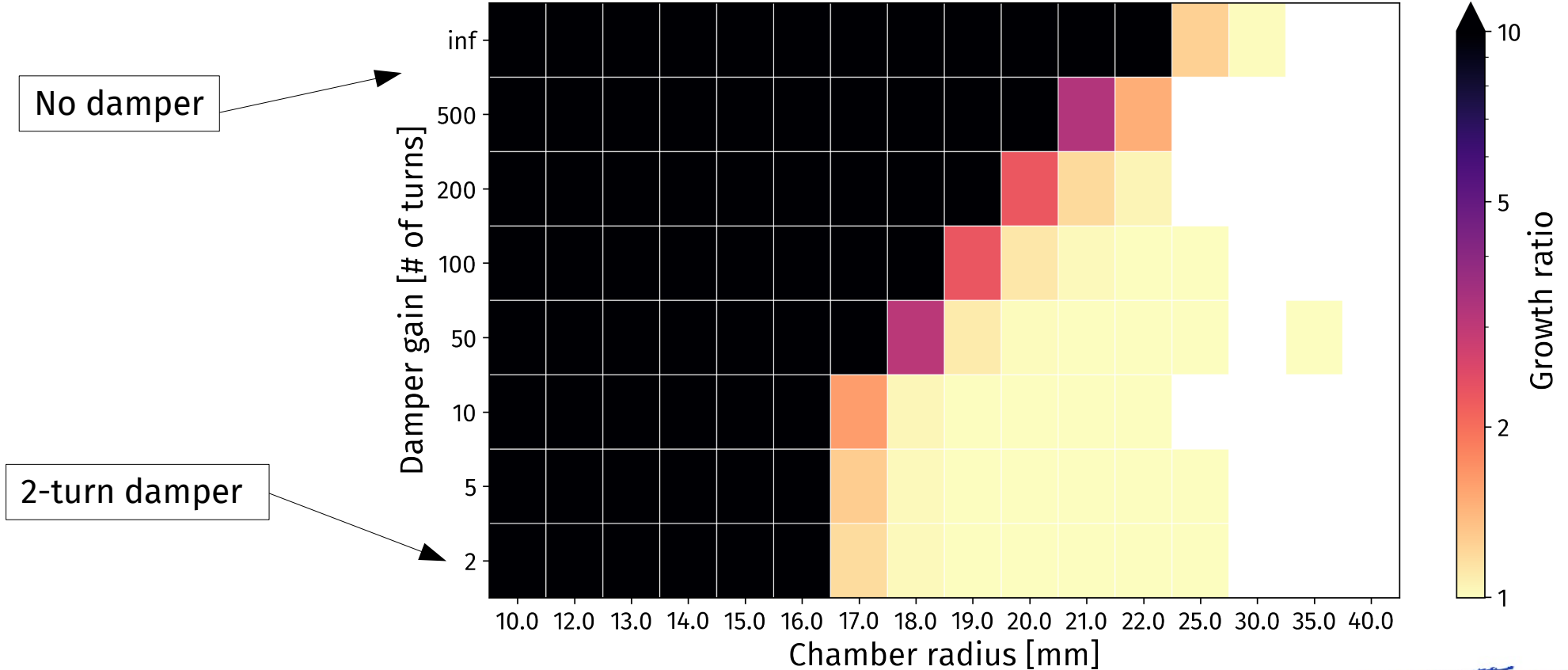
Tungsten at 300 K growth ratio after 2000 turns



Tungsten 300 K, after 2000 turns, with muon decay

decay

Tungsten at 300 K, with muon decay growth ratio after 2000 turns



Appendix: 10TeV collider

Impedance simulations parameters: materials

- Infinite thickness for all the chambers simulated

Copper at 80 K

	Unit	Value
Magnetic field	T	7
Temperature	K	80
RRR		70
DC resistivity	nOhm m	2.35

Copper at 300 K

	Unit	Value
Magnetic field	T	7
Temperature	K	300
RRR		70
DC resistivity	nOhm m	17.9

Tungsten at 80 K

	Unit	Value
Temperature	K	80
DC resistivity	nOhm m	6.06

Tungsten at 300 K

	Unit	Value
Temperature	K	300
DC resistivity	nOhm m	54.4

Stability simulation parameters

Machine parameters

	Unit	Value
Circumference	m	10000
Beam momentum	GeV/c	5000
Rev. frequency	kHz	30
RF frequency	MHz	800
Harmonic number		26685
RF voltage	MV	3200
α_p		-2.0e-6
Avg. beta x/y	m	85 / 51
Chromaticity Q'_x/Q'_y		0 / 0
Detuning from octupoles x/y	m^{-1}	0 / 0

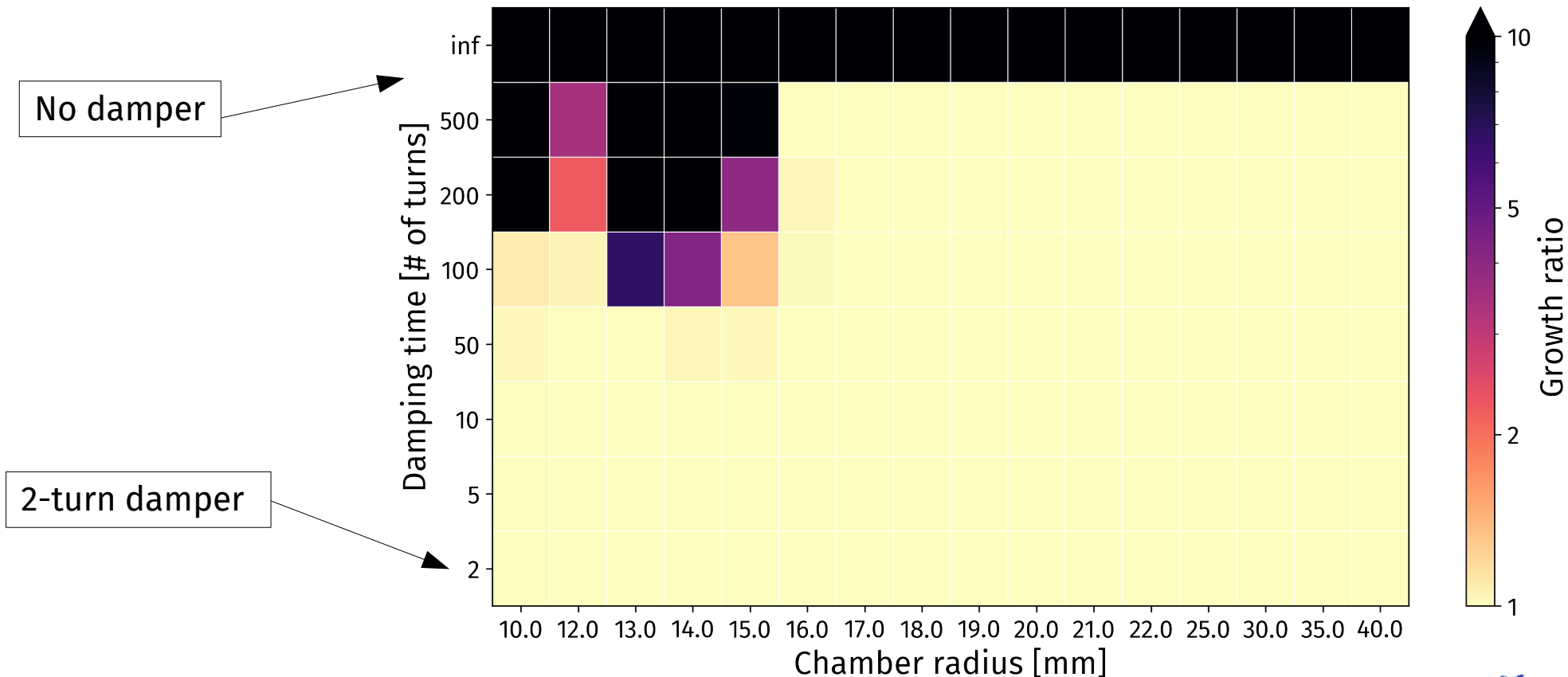
	Unit	Value
Synchrotron tune Q_s		0.00233
Synchrotron period	turns	429
Bunch length 1σ	mm	5
Bunch intensity	Particles per bunch	1.8e12
ϵ_x / ϵ_y	$\mu\text{m rad}$	25
# of macroparticles		20000

Scanned parameters

	Unit	Value
Chamber radius	mm	10 to 40
Transverse damper		2 to 500 turns/No damper

Copper 80 K, after 2000 turns

Copper at 80 K growth ratio after 5000 turns

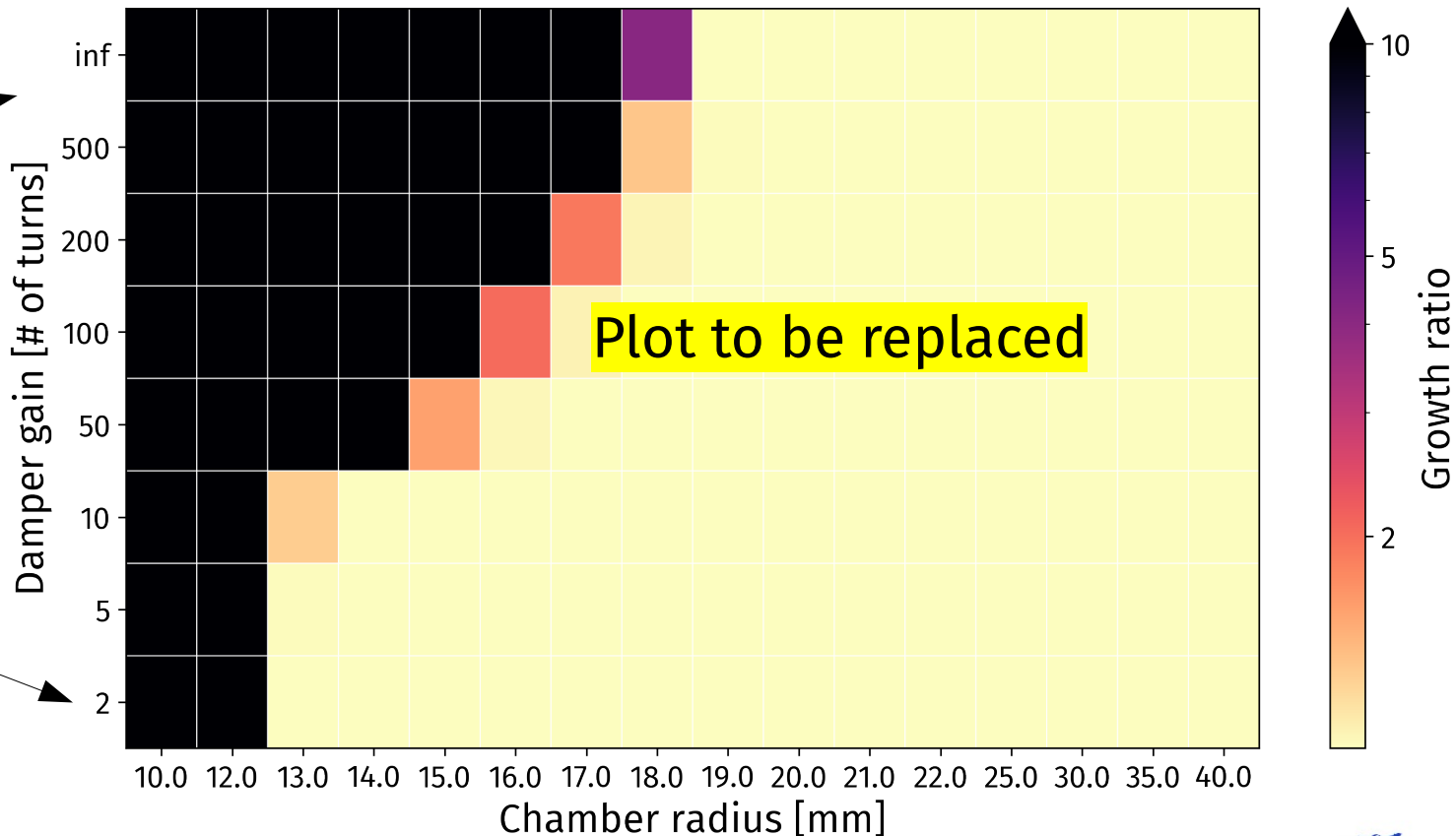


Copper 80 K, after 2000 turns, with muon decay

Copper at 300 K, with muon decay growth ratio after 2000 turns

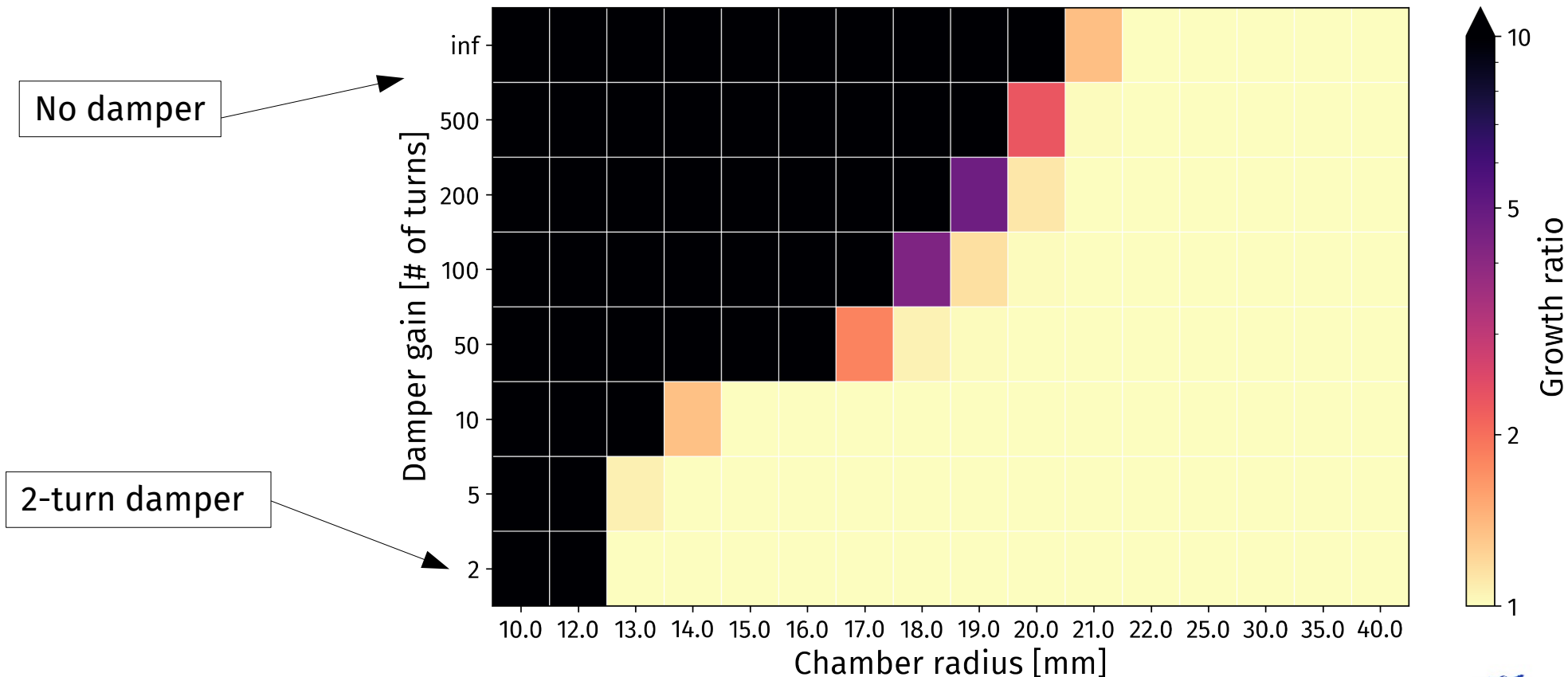
No damper

2-turn damper



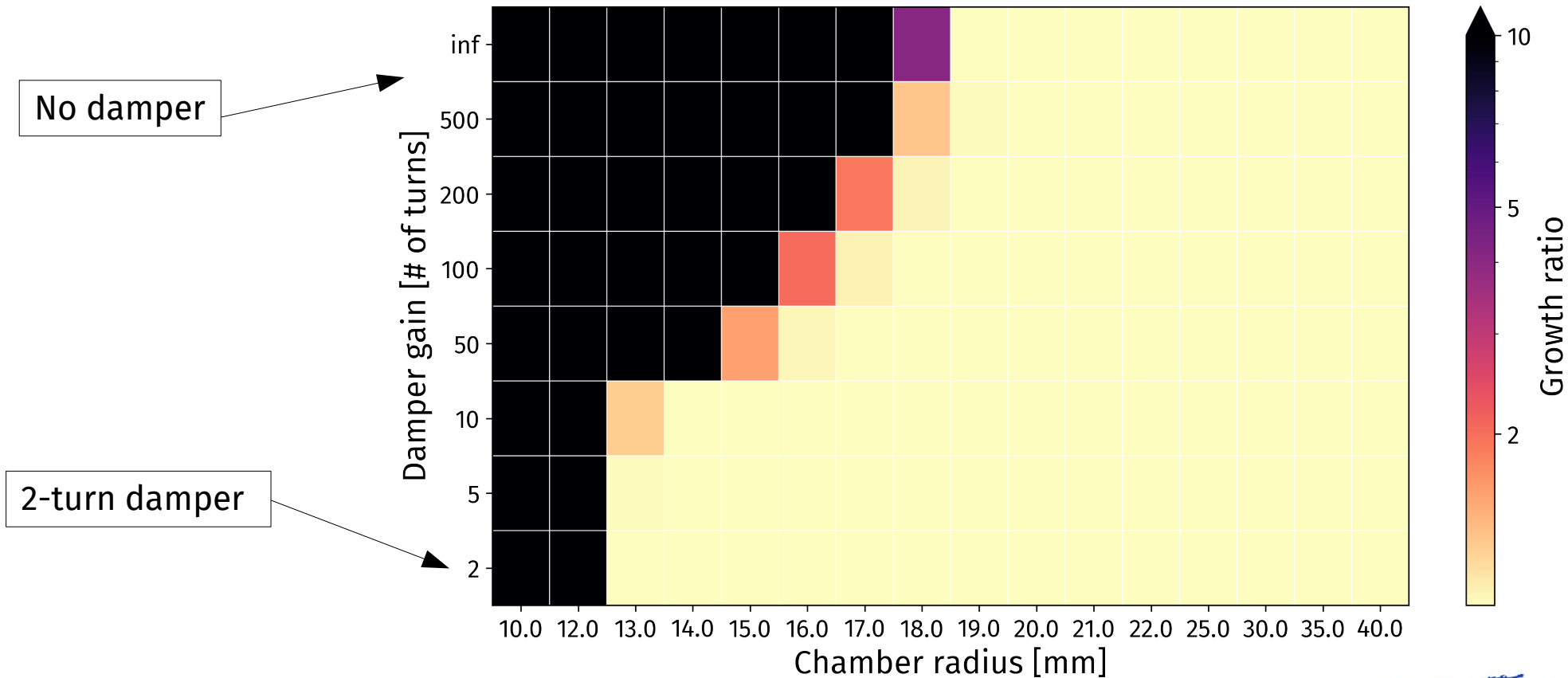
Copper 300 K, after 2000 turns

Copper at 300 K growth ratio after 2000 turns



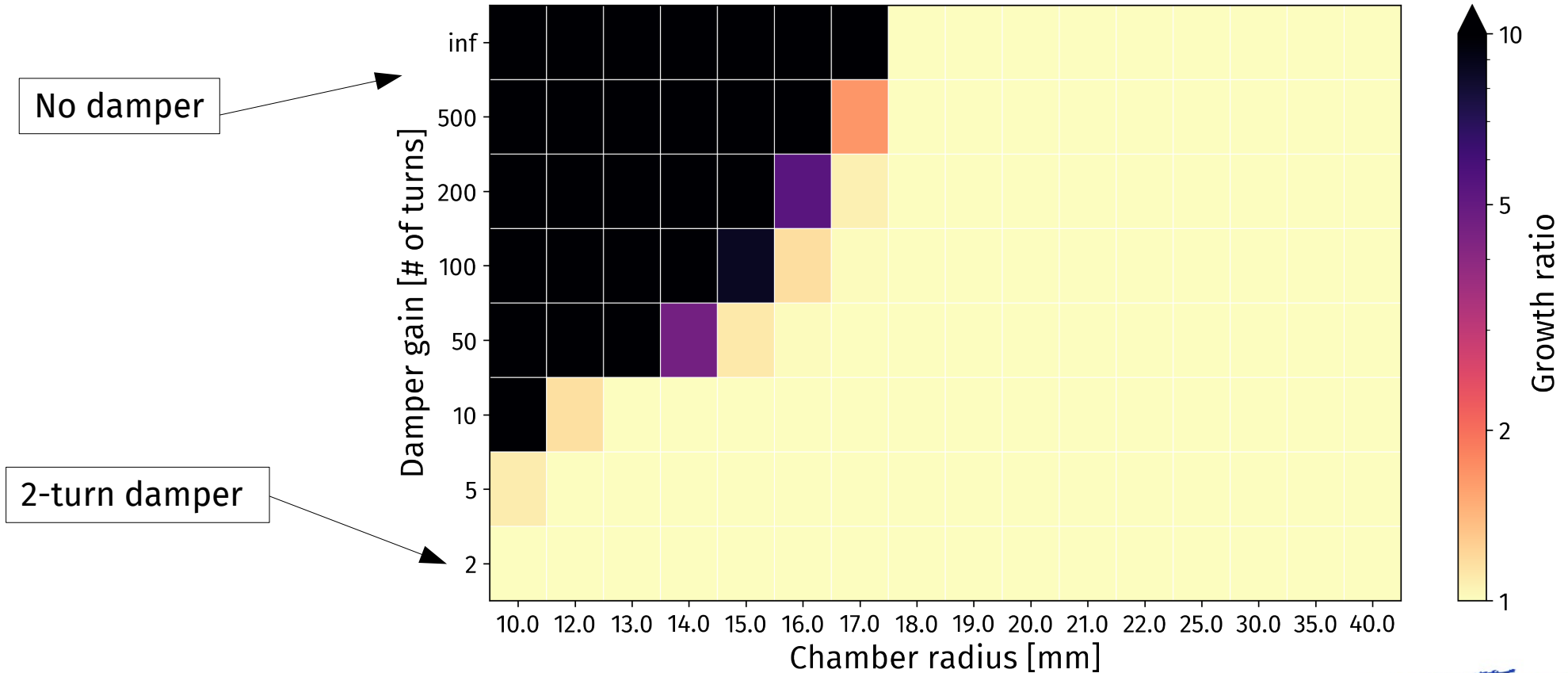
Copper 300 K, after 2000 turns, with muon decay

Copper at 300 K, with muon decay growth ratio after 2000 turns



Tungsten 80 K, after 2000 turns

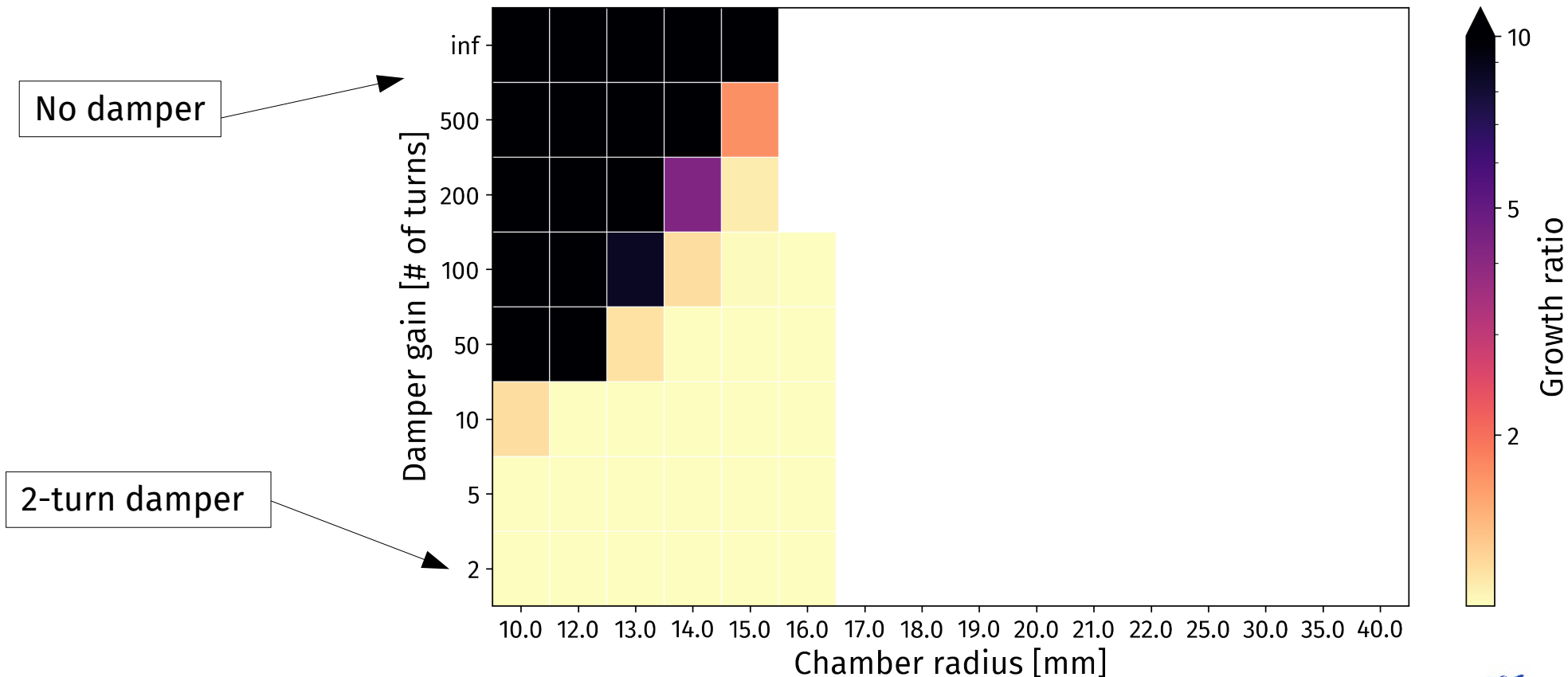
Tungsten at 80 K growth ratio after 2000 turns



Tungsten 80 K, after 2000 turns, with muon decay

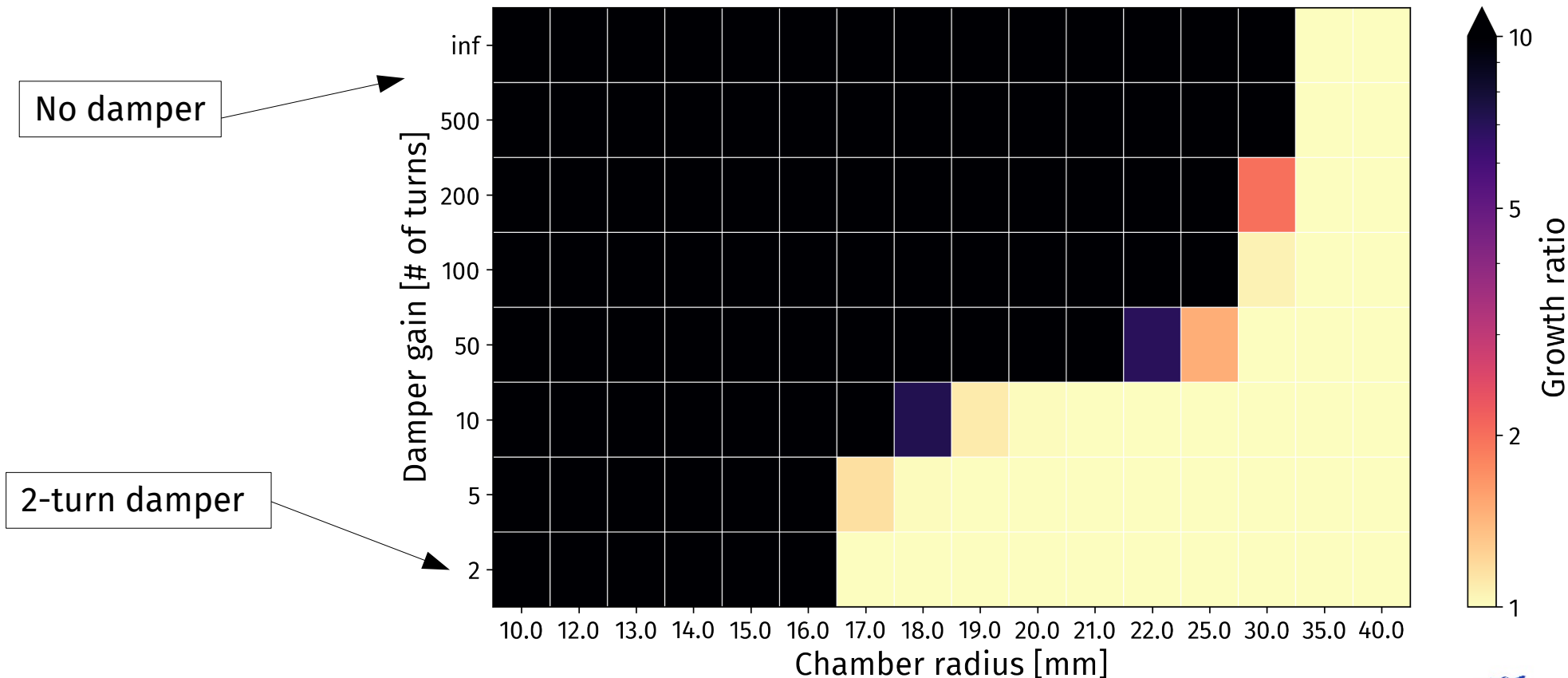
decay

Tungsten at 80 K, with muon decay growth ratio after 2000 turns



Tungsten 300 K, after 2000 turns

Tungsten at 300 K growth ratio after 2000 turns



Tungsten 300 K, after 2000 turns, with muon decay

decay

Tungsten at 300 K, with muon decay growth ratio after 2000 turns

